



ConnectCore MP13

System-on-module

Hardware Reference Manual

Revision history—90002551

Revision	Date	Description
1P	March 2023	Initial draft.
2P	May 2023	Changed VSYS minimum voltage; added note regarding data matrix on SOM label.
A	October 2023	Added certifications.

Trademarks and copyright

Digi, Digi International, and the Digi logo are trademarks or registered trademarks in the United States and other countries worldwide. All other trademarks mentioned in this document are the property of their respective owners.

© 2023 Digi International Inc. All rights reserved.

Disclaimers

Information in this document is subject to change without notice and does not represent a commitment on the part of Digi International. Digi provides this document “as is,” without warranty of any kind, expressed or implied, including, but not limited to, the implied warranties of fitness or merchantability for a particular purpose. Digi may make improvements and/or changes in this manual or in the product(s) and/or the program(s) described in this manual at any time.

Warranty

To view product warranty information, go to the following website:

www.digi.com/howtobuy/terms

Customer support

Gather support information: Before contacting Digi technical support for help, gather the following information:

- Product name and model
- Product serial number (s)
- Firmware version
- Operating system/browser (if applicable)
- Logs (from time of reported issue)
- Trace (if possible)
- Description of issue

Steps to reproduce

Contact Digi technical support: Digi offers multiple technical support plans and service packages. Contact us at +1 952.912.3444 or visit us at www.digi.com/support.

Feedback

To provide feedback on this document, email your comments to

techcomm@digi.com

Include the document title and part number (ConnectCore MP13 System-on-Module, 90002551 A) in the subject line of your email.

Contents

About the ConnectCore MP13

Features and functionality	6
Safety instructions	7
Block diagrams	7
ConnectCore MP13 module	8
STMicroelectronics STM32MP13x application processor	9
Power interfaces	10
System-on-module power architecture	10
Reference power diagram	11
Electrical characteristics	11
Bootstrap	13
Wireless interfaces	13
WLAN IEEE 802.11a/b/g/n/ac	13
RF channels	15
Transmit power	18
Antenna ports	18
Bluetooth	18

Module pinout

External signals and pin multiplexing	19
Castellated pad signals and multiplexing	21
LGA pad signals and multiplexing	35

Module specifications

Mechanical specifications	74
Host PCB footprint and cutout	74
Label	74
Environmental specifications	75
Socket options	75

Regulatory information and certifications

United States FCC	77
Labeling requirements	77
Maximum power and frequency specifications (FCC)	77
FCC notices	78
FCC-approved antennas	78

RF exposure	81
Operating frequency	81
Europe and UK	81
CE mark	82
CE and UKCA OEM labeling requirements	82
Declarations of Conformity	83
Approved antennas	83
Canada (IC)	84
Canadian Notice	85
Labeling requirements	85
Transmitters with detachable antennas	85
RF exposure	86
Approved antennas	86
Japan	86
Approval Label (MIC Marking)	87

About the ConnectCore MP13

The Digi ConnectCore® MP13 System-on-Module (SOM) platform is a highly integrated, cost-effective, connected, secure embedded solution, built on the STM32MP13x MPU family. It integrates memory, power management, the Digi Microcontroller Assist™, pre-certified wireless connectivity and advanced Digi TrustFence device security with a complete, open-source Linux software platform based on the Yocto Project.

Features and functionality

The ConnectCore MP13 system-on-module is based on the STM32MP133C processor from STMicroelectronics. This processor offers a number of interfaces, most of them multiplexed and not available simultaneously. The module has the following features:

- STM32MP133C ARM Cortex-A7:
 - Cortex-A7 operating at up to 650 MHz.
 - 32 KB L1 instruction cache.
 - 32 KB L1 data cache.
 - 128 KB level 2 unified coherent cache.
- Up to 256 MB, 16-bit DDR3 memory.
- Up to 256 MB, 8-bit SLC NAND flash memory.
- STPMIC1D Power Management IC (PMIC):
 - x4 adjustable buck SMPS converter.
 - x1 boost SMPS.
 - x1 USB OTG compliant power switch.
 - x1 general purpose power switch.
 - x4 adjustable general purpose LDOs.
 - x1 DDR3/general purpose LDO.
 - x1 USB PHY LDO.
- IEEE 802.11 a/b/g/n/ac WLAN interface.
- Bluetooth version 5.0.
- Debug interfaces:
 - System JTAG controller for STM32MP135F.
- STM32MP133C interfaces:
 - x5 I2C.
 - x4 UART.
 - x4 USART.
 - x5 SPI, four I2Ss full-duplex master/slave.
 - x2 SAI.
 - x1 SPDIF Rx.

- x2 SDMMC.
- x1 USB OTG high-speed controller.
- x1 USB high-speed Host with two ports, two high-speed PHYs. The second high-speed PHY can be shared between the USB high-speed Host and the USB OTG high-speed.
- x2 FDCAN.
- x2 Gigabit Ethernet.
- x1 Flexible memory control (FMC) interface.
- x1 Quad-SPI Flash memory interface.
- x2 ADCs with 12-bit max resolution
- x1 digital filter for sigma delta modulator (DFSDM) with 4 channels and 2 filters.

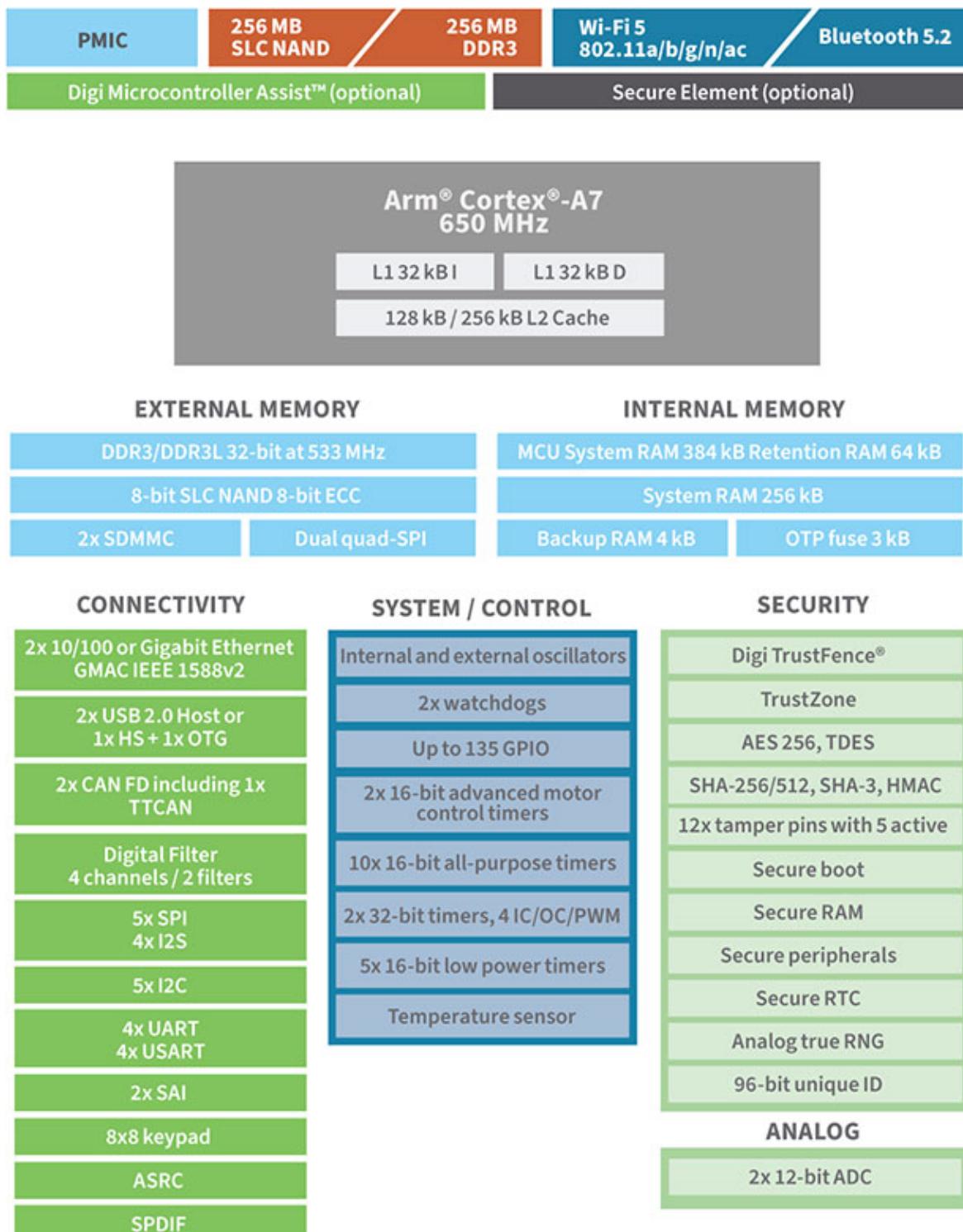
Safety instructions

- The ConnectCore MP13 module cannot be guaranteed operation due to the radio link and so should not be used for interlocks in safety critical devices such as machines or automotive applications.
- The ConnectCore MP13 module has not been approved for use in (this list is not exhaustive):
 - nuclear applications
 - explosive or flammable atmospheres
- There are no user serviceable components inside the ConnectCore MP13 module. Do not modify the ConnectCore MP13 in any way. Modifications may exclude the module from any warranty and can cause the ConnectCore MP13 to operate outside of regulatory compliance for a given country, leading to the possible illegal operation of the radio.
- Use industry standard ESD protection when handling the ConnectCore MP13 module.
- Take care while handling to avoid electrical damage to the PCB and components.
- Do not expose ConnectCore MP13 module to water or moisture.
- Use this product with the antennas specified in the ConnectCore MP13 module user guides.

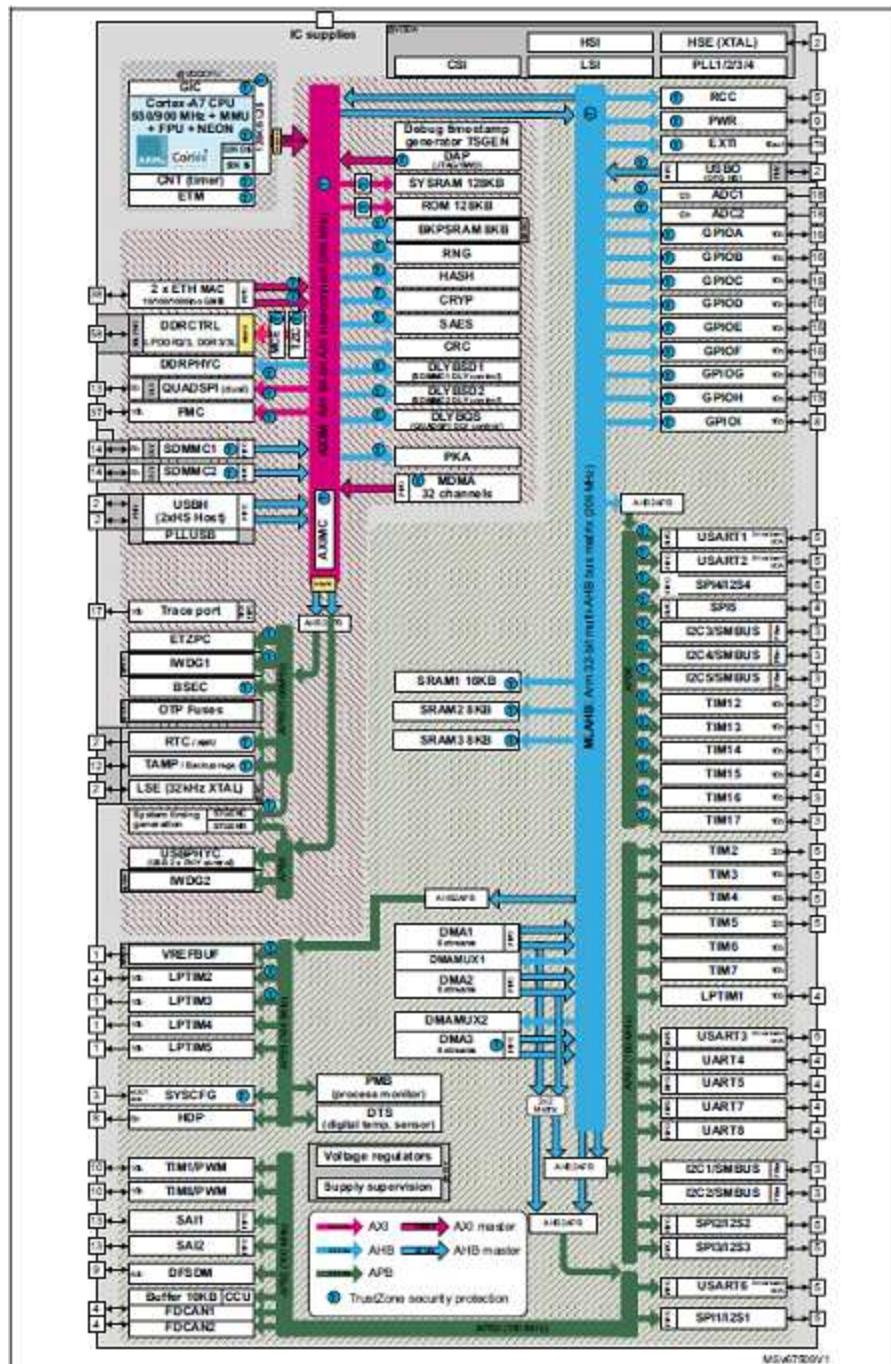
Block diagrams

The figures below show block diagrams of the ConnectCore MP13 module and of the STMicroelectronics STM32MP13x application processor.

ConnectCore MP13 module



STMicroelectronics STM32MP13x application processor



Power interfaces

System-on-module power architecture

The ConnectCore MP13 requires two primary power supply inputs: VSYS and VSYS2, which are the input power supplies to the on-module ST STPMIC1 power management IC (PMIC) that generates all required supply voltages for the module as well as the external interfaces.

The following table summarizes the PMIC regulators and switches on the ConnectCore MP13 SOM:

PMIC regulator	SOM power rail name	Input power supply	Internally used	Externally available
BUCK1	-	VSYS2	YES	NO
BUCK2	-	VSYS2	YES	NO
BUCK3	VDD	VSYS	YES	YES
BUCK4	-	VSYS	YES	NO
LDO1	-	VSYS	YES	NO
LDO2	2V8	VSYS	NO	YES
LDO3*	LDO3	-	NO	YES
LDO4	-	VSYS	YES	NO
LDO5	VDD_SD	VSYS	NO	YES
LDO6	1V8	VSYS	NO	YES
PWR_USB_SW	VBUS_OTG	-	NO	YES
PWR_SW	VBUS_SW	-	NO	YES
DDR_REF	-	VSYS2	YES	NO
BOOST	-	VSYS	YES	NO

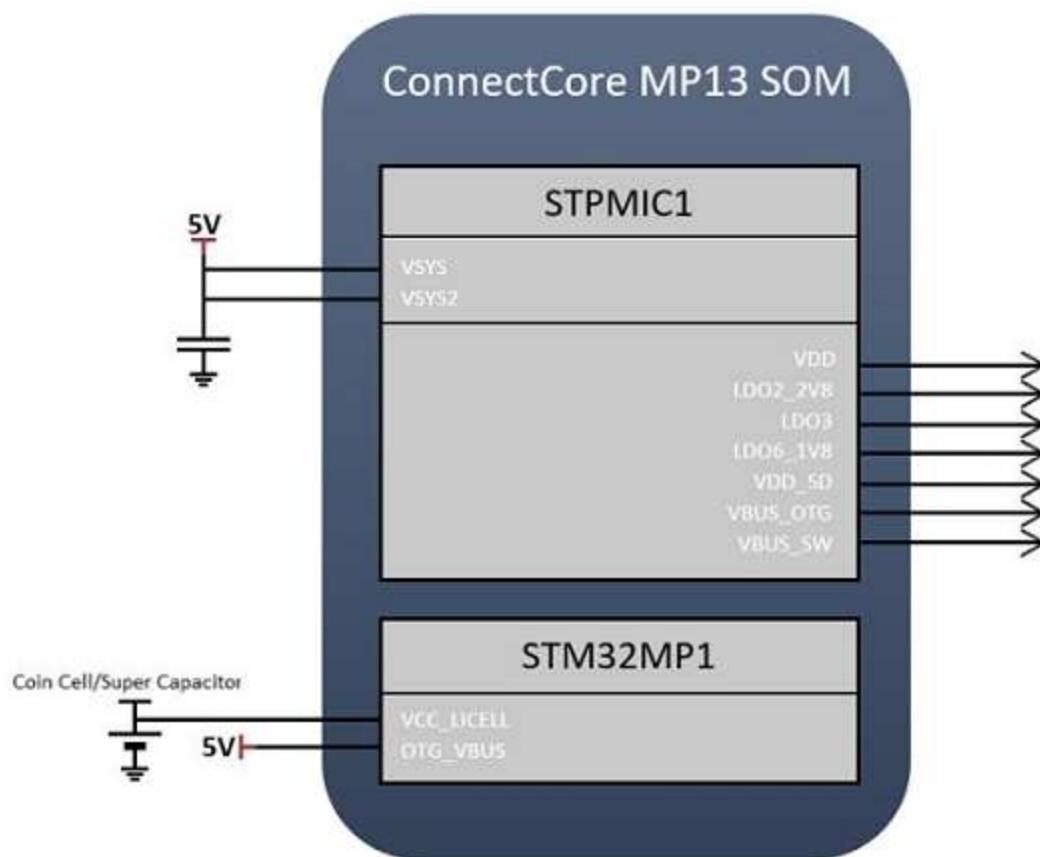
* This regulator is not available in initial versions of the module.

In addition to the input power supplies of the PMIC, other power domains of the SOM must also be set externally. This allows power management flexibility so you can adapt the input voltage of the different interfaces. The following table lists the input power rails that must be powered externally to the SOM together with the devices/power domains they power:

Input rail	Internally connected to	Description
VCC_LICELL	STM32MP1 CPU, VBAT	Support for RTC, backup registers, RAM retention and backup SRAM on the CPU.
OTG_VBUS	STM32MP1 CPU, OTG_VBUS	

Reference power diagram

The following diagram represents the power architecture of the ConnectCore MP13 module in a typical application:



Electrical characteristics

Input power rails

The following table lists the electrical specifications of all input power rails for the ConnectCore MP13:

Device	SOM power rail	Input voltage (V)		
		Minimum	Typical	Maximum
PMIC	VSYS	3.7	-	5.5
	VSYS2	2.8	-	5.5
CPU	VCC_LICELL	1.4	-	3.6
	OTG_VBUS	Vss-0.3 ¹	-	6.0 ¹

¹ Absolute maximum ratings.

Output power rails

The following table lists the electrical specifications of all output power rails for the ConnectCore MP13:

SOM power rail	Used internally in the SOM	Output voltage			Accuracy (%)		Continuous output current (mA) ¹	Turn-on time (us)		Turn-off time (ms)	
		Min	Typ	Max	Min	Max		Typ	Max	Max	Max
VDD	YES	-	3.3	-	-4	4	500	235	400	1.5	
VDD_SD	NO	1.7	-	3.9	-2	2	350	160	-	3	
LDO2_2V8	NO	1.7	-	3.3	-2	2	350	160	-	3	
LDO6_1V8	NO	0.9	-	3.3	-2	2	150	100	-	3	
LDO3	NO	1.8	-	3.3	-2	2	100	200	-	3	
VBUS_OTG	NO	-	-	-	-	-	500	3000	-	3	
VBUS_SW	NO	-	-	-	-	-	1000	3000	-	3	

Note Some of the electrical characteristics may depend on the configuration and operation mode of the different regulators. For a complete description of the electrical characteristics of the different output power rails (PMIC regulators), see the STPMIC1 datasheet.

¹ The maximum output current involves both external and internal circuitry. For those regulators that are used internally in the SOM, the current available outside will be lower.

Bootstrap

The ConnectCore MP13 module can be configured to boot from different devices and interfaces as determined by the boot ROM. The configuration of the booting process of the CPU is done through the BOOT pin and OTP bytes.

BOOT2	BOOT1	BOOT0	Boot mode
0	0	0	UART and USB port 1
0	0	1	Serial NOR Flash
0	1	0	eMMC (default SDMMC2)
0	1	1	NAND Flash
1	0	0	Reserved
1	0	1	SD card (default SDMMC1)
1	1	0	UART and USB port 2
1	1	1	Serial NAND Flash

Wireless interfaces

The ConnectCore MP13 System-on-module combines a wireless local area network (WLAN) and Bluetooth dual solution to support IEEE802.11 a/b/g/n/ac WLAN standards and Bluetooth 5, enabling seamless integration of WLAN/Bluetooth and Low Energy technology. Digi also offers a non-wireless variant of the ConnectCore MP13 module.

The following sections include specifications for the wireless interfaces available on the ConnectCore MP13 module.

WLAN IEEE 802.11a/b/g/n/ac

The following sections specify the performance of the WLAN IEEE 802.11a/b/g/n/ac interface on the ConnectCore MP13 module.

Modulation and data rates

The following tables list modulation values for the ConnectCore MP13 module, which supports the following WLAN standards:

Mode	Modulation & coding	Rate
802.11b	DBPSK	1 Mbps
	DQPSK	2 Mbps
	CCK	5.5 Mbps
	CCK	11 Mbps

Mode	Modulation & coding	Rate
802.11ga	BPSK-1/2	6 Mbps
	BPSK-3/4	9 Mbps
	QPSK-1/2	12 Mbps
	QPSK-3/4	18 Mbps
	16QAM-1/2	24 Mbps
	16QAM-3/4	36 Mbps
	64QAM-2/3	48 Mbps
	64QAM-3/4	54 Mbps
802.11n	BPSK-1/2	MCS0
	QPSK-1/2	MCS1
	QPSK-3/4	MCS2
	16QAM-1/2	MCS3
	16QAM-3/4	MCS4
	64QAM-2/3	MCS5
	64QAM-3/4	MCS6
	64QAM-5/6	MCS7
802.11ac	BPSK-1/2	MCS0
	QPSK-1/2	MCS1
	QPSK-3/4	MCS2
	16QAM-1/2	MCS3
	16QAM-3/4	MCS4
	64QAM-2/3	MCS5
	64QAM-3/4	MCS6
	64QAM-5/6	MCS7
	256QAM-3/4	MCS8
	256QAM-5/6	MCS9

Data rate (Mbps) - Non Short Guard Interval (Non-SGI)

Data rate (Mbps)		802.11b		802.11ga		802.11n		802.11ac		
		DBPSK	CCK	BPSK-1/2	64QAM-3/4	BPSK-1/2	64QAM-5/6	BPSK-1/2	64QAM-5/6	256QAM-5/6
Modulation		1 Mbps	11 Mbps	6 Mbps	54 Mbps	MCS0	MCS7	MCS0	MCS7	MCS9
2.4 GHz	HT20	1	11	6	54	6.5	65	6.5	65	
	HT40					13.5	135	13.5	135	180
5 GHz	HT20			6	54	6.5	65	6.5	65	
	HT40					13.5	135	13.5	135	180
	HT80							29.3	292.5	390

Data rate (Mbps) - Short Guard Interval (SGI)

Mode		802.11b		802.11ga		802.11n		802.11ac		
		DBPSK	CCK	BPSK-1/2	64QAM-3/4	BPSK-1/2	64QAM-5/6	BPSK-1/2	64QAM-5/6	256QAM-5/6
Modulation		1 Mbps	11 Mbps	6 Mbps	54 Mbps	MCS0	MCS7	MCS0	MCS7	MCS9
2.4 GHz	HT20	1	11	6	54	7.2	72.2	7.2	72.2	
	HT40					15	150	15	150	200
5 GHz	HT20			6	54	7.2	72.2	7.2	72.2	
	HT40					15	150	15	150	200
	HT80							32.5	325	433.3

RF channels

The ConnectCore MP13 module supports the following frequency bands:

RF band	Ch. BW	Ch. spacing	Channel number (Center freq. MHz)
2.4 GHz	20 MHz	5 MHz	1(2412), 2(2417), 3(2422), 4(2427), 5(2432), 6(2437), 7(2442), 8(2447), 9(2452), 10(2457), 11(2462), 12(2467), 13(2472), 14(2484)
	40 MHz	5 MHz	3(2422), 11(2462)

RF band	Ch. BW	Ch. spacing	Channel number (Center freq. MHz)
5 GHz	20 MHz	20 MHz	36(5180), 40(5200), 44(5220), 48(5240), 52(5260), 56(5280), 60(5300), 64 (5320), 100(5500), 104(5520), 108(5540), 112(5560), 116(5580), 120 (5600), 124(5620), 128(5640), 132(5660), 136(5680), 140(5700), 144 (5720), 149(5745), 153(5765), 157(5785), 161(5805), 165(5825)
	40 MHz	40 MHz	38(5190), 46(5230), 54(5270), 62(5310), 102(5510), 110(5550), 118(5590), 126(5630), 134(5670), 142(5710), 151(5755), 159(5795)
	80 MHz	80 MHz	42(5210), 58(5290), 106(5530), 122(5610), 138(5690), 155(5775)

Note Dependent upon regulatory bodies.

2.4 GHz

2.4 GHz band channel #	Center frequency (MHz)	EUROPE (ETSI)	NORTH AMERICA (FCC)	JAPAN
1	2412	✓	✓	✓
2	2417	✓	✓	✓
3	2422	✓	✓	✓
4	2427	✓	✓	✓
5	2432	✓	✓	✓
6	2437	✓	✓	✓
7	2442	✓	✓	✓
8	2447	✓	✓	✓
9	2452	✓	✓	✓
10	2457	✓	✓	✓
11	2462	✓	✓	✓
12	2467	✓	No	✓
13	2472	✓	No	✓
14	2484	No	No	802.11b only

5 GHz

5 GHz band channel #	Center frequency (MHz)	EUROPE (ETSI)	NORTH AMERICA (FCC)	JAPAN
36	5180	Indoors	✓	✓
40	5200	Indoors	✓	✓
44	5220	Indoors	✓	✓
48	5240	Indoors	✓	✓
52	5260	Indoors / DFS / TPC	DFS	DFS / TPC
56	5280	Indoors / DFS / TPC	DFS	DFS / TPC
60	5300	Indoors / DFS / TPC	DFS	DFS / TPC
64	5320	Indoors / DFS / TPC	DFS	DFS / TPC
100	5500	DFS / TPC	DFS	DFS / TPC
104	5520	DFS / TPC	DFS	DFS / TPC
108	5540	DFS / TPC	DFS	DFS / TPC
112	5560	DFS / TPC	DFS	DFS / TPC
116	5580	DFS / TPC	DFS	DFS / TPC
120	5600	DFS / TPC	DFS	DFS / TPC
124	5620	DFS / TPC	DFS	DFS / TPC
128	5640	DFS / TPC	DFS	DFS / TPC
132	5660	DFS / TPC	DFS	DFS / TPC
136	5680	DFS / TPC	DFS	DFS / TPC
140	5700	DFS / TPC	DFS	DFS / TPC
149	5745	SRD	✓	No Access
153	5765	SRD	✓	No Access
157	5785	SRD	✓	No Access
161	5805	SRD	✓	No Access
165	5825	SRD	✓	No Access

Note

DFS = Dynamic Frequency Selection

TPC = Transmit Power Control

SRD = Short Range Devices 25 mW max power

Transmit power

The following table lists nominal transmit power values for the ConnectCore MP13 module based on Murata LBEE5PK2AE-564 specification.

RF band	Standard	Output power (dBm)
2.4 GHz	802.11b	17 (1Mbps) - 17 (11Mbps)
	802.11g	16 (6Mbps) - 16 (54Mbps)
	802.11n	16 (MCS0) - 14 (MCS7)
5 GHz	802.11a	13 (6Mbps) - 14 (54Mbps)
	802.11n (HT20)	16 (MCS0) - 14 (MCS7)
	802.11ac (VHT20)	16 (MCS0) - 13 (MCS8)
	802.11n (HT40)	14 (MCS0) - 13 (MCS7)
	802.11ac (VHT40)	14 (MCS0) - 11 (MCS9)
	802.11ac (VHT80)	13 (MCS0) - 12 (MCS9)

Antenna ports

The ConnectCore MP13 module has one antenna port on the module via a dedicated U.FL connector. The antenna port supports WLAN and Bluetooth functionality.

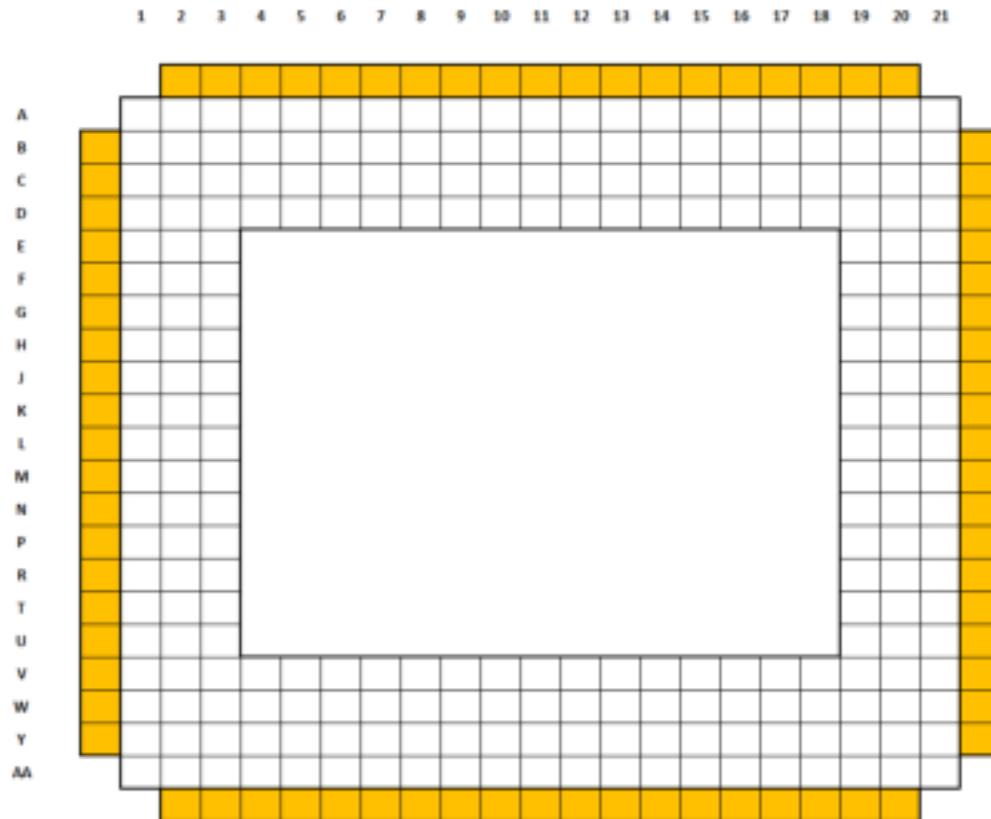
Bluetooth

The ConnectCore MP13 module supports both Bluetooth and Bluetooth Low Energy protocols:

- Bluetooth 5 with all Bluetooth 4.2 optional features. Bluetooth class 1 and class 2 transmitter operation.
- Integrated WLAN-Bluetooth coexistence.

Module pinout

The ConnectCore MP13 module has a mixed pad structure. The module provides 245 LGA pins, 76 of them connected to the peripheral castellated pads. The general layout can be found on the following diagram:



White cells: LGA pads

Orange cells: castellated pads

Note Pad A1 is unconnected. This pad is meant for module-orientation purposes; its shape is square, whereas all other pads are circular. Pad A1 should not be soldered down to a corresponding pad on the carrier board.

External signals and pin multiplexing

The following tables provide the pinout information of the ConnectCore MP13 module. For additional information related to the signals listed in the table, refer to the STMicroelectronics STM32MP1 technical documentation.

Note The Digi ConnectCore Smart IOmux tool can dramatically simplify pin configuration and resolution. You can enter the list of interfaces required by your project and use the Smart IOmux graphical interface to mock up configuration options, resulting in full pin assignment and device tree snippets that match your desired functionality. See the [Smart IOmux User Guide](#) for more information and download instructions.

The microprocessor used on this module, like all CMOS devices, can be driven into a latch-up condition if any I/O pin is driven outside of its associated power rail. Care must be taken to:

- Never drive an I/O pin beyond its positive rail or below ground.
- Never drive an I/O pin from an external power source during the power-on or reset sequences.
- Never hot-swap the module or interrupt its ground connection to external circuitry.



Latch-up is a condition that can cause excessive current draw and result in excessive heating of the microprocessor or its power supplies. This excessive heating can permanently damage the microprocessor and/or its supporting components.

When you use an external supply on the carrier board supporting the ConnectCore MP13 module, make sure this supply is NOT back driving STM32MP1 I/Os while their power rails are not enabled. For example, this can happen when an external 3.3V supply is available on the carrier board and this supply powers components driven by STM32MP1 I/Os. In this case, Digi recommends you enable the external power supply after internal 3.3V is enabled, or add the necessary protection circuitry to avoid back voltage (leakage).

Castellated pad signals and multiplexing

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
1 / B1	CPAD1	VCC_LICELL	VBAT	-	-	VCC_LICELL	Coin cell supply.
2 / C1	CPAD2	VSYS	-	-	-	VSYS	Input power line.
3 / D1	CPAD3	NC	-	-	-	NC	
4 / E1	CPAD4	NC	-	-	-	-	
5 / F1	CPAD5	GND	-	-	-	-	
6 / G1	CPAD6	VSYS	-	-	-	VSYS	Input power line.
7 / H1	CPAD7	VSYS2	-	-	-	VSYS2	Input power line.
8 / J1	CPAD8	GND	-	-	-	-	
9 / K1	CPAD9	VDD	-	-	-	VDD	Output power line.
10 / L1	CPAD10	NC	-	-	-	-	
11 / M1	CPAD11	NC	-	-	-	-	
12 / N1	CPAD12	NC	-	-	-	-	
13 / P1	CPAD13	NRST	NRST	-	-		Reset line of the CPU. Recommendation: leave this pin floating.
14 / R1	CPAD14	I2S1_WS	PA4	AF2: TIM5_ETR AF3: USART2_CK AF4: SAI1_SCK_B AF5: SPI1_NSS/I2S1_-	ADC1_INP14	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				WS AF6: DFSDM1_CKIN1 AF10: ETH1_PPS_OUT AF11: ETH2_PPS_OUT AF12: SAI1_SCK_A			
15 / T1	CPAD15	I2S1_CK	PC3	AF2: SAI1_CK1 AF3: DFSDM1_CKOUT AF5: SPI1_MISO/I2S1_SD AF6: SPI1_SCK/I2S1_CK AF8: UART5_CTS AF10: SAI1_MCLK_A AF11: ETH1_MII_TX_CLK AF12: ETH2_MII_TX_CLK	ADC1_INP13 ADC1_INN12 TAMP_IN5	VDD	
16 / U1	CPAD16	SDMMC1_D1	PC9	AF0: TRACED1 AF2: TIM3_CH4 AF3: TIM8_CH4 AF7: USART3_RTS AF8: UART5_CTS AF9: FDCAN1_TX AF12: SDMMC1_D1 AF14: LCD_B4	-	VDD	
17 / V1	CPAD17	SDMMC1_CMD	PD2	AF0: TRACED4 AF2: TIM3_ETR AF4: I2C1_SMBA AF5: SPI3_NSS/I2S3_WP AF6: SAI2_D1 AF7: USART3_RX AF12: SDMMC1_CMD	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
18 / W1	CPAD18	PA13	PA13	AF0: DBTRGO AF1: DBTRGI AF2: MCO1 AF8: UART4_TX	BOOTFAILN	VDD	
19 / Y1	CPAD19	BOOT1	BOOT1	-	-	VDD	
20 / AA2	CPAD20	SDMMC1_D0	PC8	AF0: TRACED0 AF2: TIM3_CH3 AF3: TIM8_CH3 AF5: SPI3_MISO/I2S3_SD AF7: USART6_CK AF8: USART3_CTS AF10: SAI2_FS_B AF11: UART5_RTS/UART5_DE AF12: SDMMC1_D0 AF14: LCD_G7	-	VDD	
21 / AA3	CPAD21	SDMMC1_CLK	PC12	AF0: TRACECLK AF8: UART7_TX AF10: SAI2_SD_B AF12: SDMMC1_CK AF14: LCD_DE	-	VDD	
22 / AA4	CPAD22	SDMMC1_D2	PC10	AF0: TRACED2 AF5: I2C1_SCL AF6: SPI3_SCK/I2S3_CK AF7: USART3_TX AF10: SAI2_MCLK_B AF12: SDMMC1_D2	-	VDD	
23 / AA5	CPAD23	SDMMC1_D3	PC11	AF0: TRACED3 AF4: I2C1_SDA	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				AF6: SPI3_MOSI/I2S3_SDO AF7: USART3_CK AF8: UART5_RX AF10: SAI2_SCK_B AF12: SDMMC1_D3			
24 / AA6	CPAD24	UART5_TX	PA0	AF1: TIM2_CH1 AF2: TIM5_CH1 AF3: TIM8_ETR AF4: TIM15_BKIN AF6: SAI1_SD_B AF8: UART5_TX AF11: ETH1_MII_CRS AF12: ETH2_MII_CRS	ADC1_INP7 ADC1_INN3 ADC2_INP7 ADC2_INN3	VDD	
25 / AA7	CPAD25	UART5_RX	PF13	AF1: TIM2_ETR AF2: SAI1_MCLK_B AF6: DFSDM1_DATIN3 AF7: USART2_TX AF8: UART5_RX	ADC1_INP11 ADC1_INN10 ADC2_INP11 ADC2_INN10	VDD	
26 / AA8	CPAD26	USB2_D_P	USB_DP2	-	USBH_HS_DP2 OTG_HS_DP		
27 / AA9	CPAD27	USB2_D_N	USB_DM2	-	USBH_HS_DM2 OTG_HS_DM		
28 / AA10	CPAD28	GND	-	-	-	-	
29 / AA11	CPAD29	OTG_VBUS	PI7	-	OTG_HS_VBUS		Input power line.
30 / AA12	CPAD30	I2S1_SDI	PA6	AF1: TIM1_BKIN AF2: TIM3_CH1 AF3: TIM8_BKIN AF4: SAI2_CK2	ADC1_INP17 ADC1_INN16 TAMP_IN2	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				AF5: SPI1_MISO/I2S1_SDI AF7: USART1_CK AF8: UART4_RTS/UART4_DE AF9: TIM13_CH1 AF12: SAI2_SCK_A			
31 / AA13	CPAD31	USB_OTG_ID	PA10	AF1: TIM1_CH3	OTG_HS_ID		
32 / AA14	CPAD32	I2S1_SDO	PA3	AF1: TIM2_CH4 AF2: TIM5_CH4 AF3: LPTIM5_OUT AF4: TIM15_CH2 AF5: SPI1_MOSI/I2S1_SDO AF6: SAI1_FS_B AF7: USART2_RX AF11: ETH1_MII_COL AF12: ETH2_MII_COL	ADC1_INP12 ADC1_INN11 PVD_IN WKUP6	VDD	
33 / AA15	CPAD33	BOOT2	BOOT2	-	-	VDD	
34 / AA16	CPAD34	JTMS-SWDIO	JTMS-SWDIO	-	-		
35 / AA17	CPAD35	USB1_D_P	USB_DP1	-	USBH_HS_DP1		
36 / AA18	CPAD36	USB1_D_N	USB_DM1	-	USBH_HS_DM1		
37 / AA19	CPAD37	ETH1_MDC	PG2	AF1: MCO2 AF3: TIM8_BKIN AF10: SAI2_MCLK_B AF11: ETH1_MDC AF13: DCMIPP_D1	-	VDD	
38 / AA20	CPAD38	ETH1_MDIO	PA2	AF1: TIM2_CH3	ADC1_INP1	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				AF2: TIM5_CH3 AF3: LPTIM4_OUT AF4: TIM15_CH1 AF7: USART2_TX AF11: ETH1_MDIO	ADC2_INP1		
39 / Y21	CPAD39	JTDO-TRACESWO	JTDO-TRACESWO	-	-		
40 / W21	CPAD40	JTCK-SWCLK	JTCK-SWCLK	-	-		
41 / V21	CPAD41	JTDI	JTDI	-	-		
42 / U21	CPAD42	JTRST	JTRST	-	-		
43 / T21	CPAD43	UART8_TX	PE4	AF1: SPI5_MISO AF2: SAI1_D2 AF3: DFSDM1_DATIN3 AF4: TIM15_CH1N AF5: I2S_CKIN AF6: SAI1_FS_A AF7: UART7_RTS/UART7_DE AF8: UART8_TX AF9: QUADSPI_BK2_NCS AF10: FMC_NCE2 AF12: FMC_A25 AF13: DCMIPP_D3 AF14: LCD_G7	-	VDD	
44 / R21	CPAD44	UART8_RX	PE0	AF6: DCMIPP_D12 AF8: UART8_RX AF9: FDCAN2_RX AF11: LCD_B1 AF12: FMC_A11	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				AF13: DCMIPP_D1 AF14: LCD_B5	-	-	
45 / P21	CPAD45	GND	-	-	-	-	
46 / N21	CPAD46	UART8_RTS	PE14	AF1: TIM1_BKIN AF4: SAI1_D4 AF8: UART8_RTS/UART8_DE AF9: QUADSPI_BK1_NCS AF10: QUADSPI_BK2_IO2 AF12: FMC_D11/FMC_AD11 AF13: DCMIPP_D7 AF14: LCD_G0	TAMP_IN6	VDD	
47 / M21	CPAD47	UART8_CTS	PG10	AF5: SPI5_SCK AF6: SAI1_SD_B AF8: UART8_CTS AF9: FDCAN1_TX AF10: QUADSPI_BK2_IO1 AF12: FMC_NE3 AF13: DCMIPP_D2	-	VDD	
48 / L21	CPAD48	ETH1_RXD0	PC4	AF2: TIM3_ETR AF3: DFSDM1_CKIN2 AF4: SAI1_D3 AF5: I2S1_MCK AF8: UART5_RTS/UART5_DE AF9: SPDIFRX_IN2 AF11: ETH1_MII_	ADC1_INP4 ADC2_INP4	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				RXD0/ETH1_RGMII_ RXD0/ETH1_RMII_RXD0 AF12: SAI2_D3			
49 / K21	CPAD49	ETH1_RX_DV	PA7	AF1: TIM1_CH1N AF2: TIM3_CH2 AF3: TIM8_CH1N AF4: SAI2_D1 AF5: SPI1_SCK/I2S1_CK AF7: USART1_ CTS/USART1_NSS AF9: TIM14_CH1 AF11: ETH1_MII_RX_ DV/ETH1_RGMII_RX_ CTL/ETH1_RMII_CRS_ DV AF12: SAI2_SD_A	ADC1_INP16	VDD	
50 / J21	CPAD50	ETH1_RX_ER	PI3	AF8: SPDIFRX_IN3 AF11: ETH1_MII_RX_ER	TAMP_IN4 TAMP_OUT5 WKUP2	VDD	
51 / H21	CPAD51	ETH1_TXD1	PG14	AF1: LPTIM1_ETR AF6: SAI2_D1 AF7: USART6_TX AF10: SAI2_SD_A AF11: ETH1_MII_ TXD1/ETH1_RGMII_ TXD1/ETH1_RMII_TXD1	-	VDD	
52 / G21	CPAD52	ETH1_TX_EN	PB11	AF1: TIM2_CH4 AF3: LPTIM1_OUT AF4: I2C5_SMBA AF7: USART3_RX AF11: ETH1_MII_TX_	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				EN/ETH1_RGMII_TX_CTL/ETH1_RMII_TX_EN			
53 / F21	CPAD53	ETH1_REF_CLK	PD7	AF0: MCO1 AF3: USART2_CK AF4: I2C2_SCL AF5: I2C3_SDA AF9: SPDIFRX_IN0 AF10: ETH1_MII_RX_CLK/ETH1_RGMII_RX_CLK/ETH1_RMII_REF_CLK AF11: QUADSPI_BK1_IO2 AF12: FMC_NE1	-	VDD	
54 / E21	CPAD54	ETH1_RXD1	PC5	AF3: DFSDM1_DATIN2 AF4: SAI2_D4 AF5: I2S_CKIN AF6: SAI1_D4 AF7: USART2_CTS/USART2 NSS AF9: SPDIFRX_IN3 AF11: ETH1_MII_RXD1/ETH1_RGMII_RXD1/ETH1_RMII_RXD1	ADC1_INP10 ADC2_INP10	VDD	
55 / D21	CPAD55	ETH1_TXD0	PG13	AF1: LPTIM1_OUT AF7: USART6_CTS/USART6_NSS AF11: ETH1_MII_TXD0/ETH1_RGMII_TXD0/ETH1_RMII_TXD0	ADC2_INP6 ADC2_INN2	VDD	
56 / C21	CPAD56	LTDC_CLK	PD9	AF0: TRACECLK	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				AF3: DFSDM1_DATIN3 AF10: SDMMC2_CDIR AF11: LCD_B5 AF12: FMC_D14/FMC_AD14 AF13: LCD_CLK AF14: LCD_B0			
57 / B21	CPAD57	LTDC_HSYNC	PE1	AF1: LPTIM1_IN2 AF8: UART8_TX AF9: LCD_HSYNC AF11: LCD_R4 AF12: FMC_NBL1 AF13: DCMIPP_D3 AF14: DCMIPP_D12	-	VDD	
58 / A20	CPAD58	LTDC_B6	PF9	AF1: TIM17_CH1N AF2: TIM1_CH1 AF3: DFSDM1_CKIN3 AF6: SAI1_D4 AF7: UART7_CTS AF8: UART8_RX AF9: TIM14_CH1 AF10: QUADSPI_BK1_IO1 AF11: QUADSPI_BK2_IO3 AF12: FMC_A9 AF14: LCD_B6	-	VDD	
59 / A19	CPAD59	NC	-	-	-	VDD	
60 / A18	CPAD60	LTDC_B2	PH7	AF2: SAI2_FS_B AF5: I2C3_SDA AF6: SPI5_SCK	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				AF9: QUADSPI_BK2_IO3 AF10: ETH2_MII_TX_CLK AF11: ETH1_MII_TX_CLK AF13: QUADSPI_BK1_IO3 AF14: LCD_B2			
61 / A17	CPAD61	LTDC_B5	PF10	AF1: TIM16_BKIN AF2: SAI1_D3 AF3: TIM8_BKIN AF5: SPI5_NSS AF7: USART6_RTS/USART6_DE AF8: UART7_RTS/UART7_DE AF9: QUADSPI_CLK AF13: DCMIPP_HSYNC AF14: LCD_B5	TAMP_IN1	VDD	
62 / A16	CPAD62	LTDC_G2	PH13	AF0: TRACED15 AF2: USART2_CK AF3: TIM8_CH1N AF4: I2C5_SCL AF6: SPI3_SCK/I2S3_CK AF8: UART4_TX AF13: LCD_G3 AF14: LCD_G2	-	VDD	
63 / A15	CPAD63	LTDC_G3	PF3	AF3: LPTIM2_IN2 AF4: I2C5_SDA AF5: SPI4_MISO/I2S4_SD AF6: SPI3_NSS/I2S3_	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				WS AF12: FMC_A3 AF14: LCD_G3			
64 / A14	CPAD64	LTDC_B7	PB6	AF0: TRACED6 AF1: TIM16_CH1N AF2: TIM4_CH1 AF3: TIM8_CH1 AF4: USART1_TX AF6: SAI1_CK2 AF7: LCD_B6 AF9: QUADSPI_BK1_NCS AF11: ETH2_MDIO AF12: FMC_NE3 AF13: DCMIPP_D5 AF14: LCD_B7 AF15: HDP6	-	VDD	
65 / A13	CPAD65	GND	-		-	-	
66 / A12	CPAD66	LTDC_B4	PH3	AF4: I2C3_SCL AF5: SPI5_MOSI AF9: QUADSPI_BK2_IO1 AF10: ETH1_MII_COL AF11: LCD_R5 AF12: ETH2_MII_COL AF13: QUADSPI_BK1_IO0 AF14: LCD_B4	-	VDD	
67 / A11	CPAD67	NC	-	-	-	VDD	
68 / A10	CPAD68	LTDC_B3	PG15	AF7: USART6_CTS/USART6 NSS	-	VDD	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
				AF8: UART7_CTS AF9: QUADSPI_BK1_IO1 AF10: ETH2_PHY_INTN AF11: LCD_B4 AF13: DCMIPP_D10 AF14: LCD_B3			
69 / A9	CPAD69	LTDC_DE	PH9	AF1: TIM1_CH4 AF2: TIM12_CH2 AF5: SPI4_SCK/I2S4_CK AF6: DCMIPP_D13 AF9: LCD_B5 AF11: LCD_DE AF12: FMC_A20 AF13: DCMIPP_D9 AF14: DCMIPP_D8	-	VDD	
70 / A8	CPAD70	VCC_MCA	-	-	-	VCC_MCA	Input power line.
71 / A7	CPAD71	SWD_DIO/MCA_IO7	-	-	-	VCC_MCA	
72 / A6	CPAD72	SWD_CLK/PWR_IO	-	-	-	VCC_MCA	Input power on/off line of the module (active low). Pull this line up to VCC_MCA.
73 / A5	CPAD73	MCA_RESET	-	-	-	VCC_MCA	Input reset line of the module (active low). Pull this line up to VCC_MCA.
74 / A4	CPAD74	MCA_VIN_DET	-	-	-	VCC_MCA	

Castellated pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP1 pad name	Alternate functions	Additional functions	Power group	Comments
75 / A3	CPAD75	MCA_IO4	-	MCA GPIO/ADC	-	VCC_MCA	
76 / A2	CPAD76	MCA_IO0	-	MCA GPIO/ADC	-	VCC_MCA	

LGA pad signals and multiplexing

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
A2	LGA_A2	MCA_IO0	-	MCA GPIO/ADC	-	VCC_MCA	
A3	LGA_A3	MCA_IO4	-	MCA GPIO/ADC	-	VCC_MCA	
A4	LGA_A4	MCA_VIN_DET	-	-	-	VCC_MCA	
A5	LGA_A5	MCA_RESET	-	-	-	VCC_MCA	Input reset line of the module (active low). Pull this line up to VCC_MCA.
A6	LGA_A6	SWD_CLK/PWR_IO	-	-	-	VCC_MCA	Input power on/off line of the module (active low). Pull this line up to VCC_MCA.
A7	LGA_A7	SWD_DIO/MCA_IO7	-	-	-	VCC_MCA	
A8	LGA_A8	VCC_MCA	-	-	-	VCC_MCA	Input power line.
A9	LGA_A9	LTDC_DE	PH9	AF1: TIM1_CH4 AF2: TIM12_CH2 AF5: SPI4_SCK/I2S4_CK AF12: FMC_A20	-	VDD	
A10	LGA_A10	LTDC_B3	PG15	AF7: USART6_	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				CTS/USART6_NSS AF8: UART7_CTS AF9: QUADSPI_BK1_IO1 AF10: ETH2_PHY_INTN			
A11	LGA_A11	NC	-	-	-	VDD	
A12	LGA_A12	LTDC_B4	PH3	AF4: I2C3_SCL AF5: SPI5_MOSI AF9: QUADSPI_BK2_IO1 AF10: ETH1_MII_COL AF12: ETH2_MII_COL AF13: QUADSPI_BK1_IO0	-	VDD	
A13	LGA_A13	GND	-	-	-		
A14	LGA_A14	LTDC_B7	PB6	AF0: TRACED6 AF1: TIM16_CH1N AF2: TIM4_CH1 AF3: TIM8_CH1 AF4: USART1_TX AF6: SAI1_CK2 AF9: QUADSPI_BK1_NCS AF11: ETH2_MDIO AF12: FMC_NE3 AF15: HDP6	-	VDD	
A15	LGA_A15	LTDC_G3	PF3	AF3: LPTIM2_IN2	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF4: I2C5_SDA AF5: SPI4_MISO/I2S4_SDII AF6: SPI3_NSS/I2S3_WS AF12: FMC_A3			
A16	LGA_A16	LTDC_G2	PH13	AF0: TRACED15 AF2: USART2_CK AF3: TIM8_CH1N AF4: I2C5_SCL AF6: SPI3_SCK/I2S3_CK AF8: UART4_TX	-	VDD	
A17	LGA_A17	LTDC_B5	PF10	AF1: TIM16_BKIN AF2: SAI1_D3 AF3: TIM8_BKIN AF5: SPI5_NSS AF7: USART6_RTS/USART6_DE AF8: UART7_RTS/UART7_DE AF9: QUADSPI_CLK	TAMP_IN1	VDD	
A18	LGA_A18	LTDC_B2	PH7	AF2: SAI2_FS_B AF5: I2C3_SDA AF6: SPI5_SCK AF9: QUADSPI_BK2_IO3 AF10: ETH2_MII_TX_CLK AF11: ETH1_MII_TX_CLK AF13: QUADSPI_-	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				BK1_IO3			
A19	LGA_A19	NC	-	-	-	VDD	
A20	LGA_A20	LTDC_B6	PF9	AF1: TIM17_CH1N AF2: TIM1_CH1 AF3: DFSDM1_ CKIN3 AF6: SAI1_D4 AF7: UART7_CTS AF8: UART8_RX AF9: TIM14_CH1 AF10: QUADSPI_ BK1_IO1 AF11: QUADSPI_ BK2_IO3 AF12: FMC_A9	-	VDD	
A21	LGA_A21	GND	-	-	-		
B1	LGA_B1	VCC_LICELL	VBAT	-	-		Coin cell supply.
B2	LGA_B2	MCA_IO1	-	MCA GPIO/ADC	-		
B3	LGA_B3	ETH2_TXD0	PF7	AF1: TIM17_CH1 AF7: UART7_TX AF8: UART4_CTS AF10: ETH1_RGMII_ CLK125 AF11: ETH2_MII_ TXD0/ETH2_RGMII_ TXD0/ETH2_RMII_ TXD0 AF12: FMC_A18	-	VDD	
B4	LGA_B4	ETH2_TXD1	PG11	AF4: SAI2_D3	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF5: I2S2_MCK AF7: USART3_TX AF8: UART4_TX AF10: ETH2_MII_TXD1/ETH2_RGMII_TXD1/ETH2_RMII_TXD1 AF12: FMC_A24			
B5	LGA_B5	MCA_IO2/EXT_VREF	-	MCA GPIO/ADC	-		
B6	LGA_B6	MCA_IO5	-	MCA GPIO/ADC	-		
B7	LGA_B7	RESERVED	-	-	-		Reserved pad.
B8	LGA_B8	ETH2_TXD2	PG1	AF1: LPTIM1_ETR AF2: TIM4_ETR AF3: SAI2_FS_A AF4: I2C2_SMBA AF5: SPI2_MISO/I2S2_SD1 AF6: SAI2_D2 AF9: FDCAN2_TX AF10: ETH2_MII_TXD2/ETH2_RGMII_TXD2 AF12: FMC_NBL0	-	VDD	
B9	LGA_B9	ETH2_TXD3	PE6	AF0: MCO2 AF1: TIM1_BKIN2 AF2: SAI2_SCK_B AF4: TIM15_CH2 AF5: I2C3_SMBA AF6: SAI1_SCK_B	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF8: UART4_RTS/UART4_DE AF11: ETH2_MII_TXD3/ETH2_RGMII_TXD3 AF12: FMC_A22			
B10	LGA_B10	ETH2_TX_EN	PF6	AF1: TIM16_CH1 AF5: SPI5_NSS AF7: UART7_RX AF9: QUADSPI_BK1_IO2 AF11: ETH2_MII_TX_EN/ETH2_RGMII_TX_CTL/ETH2_RMII_TX_EN	-	VDD	
B11	LGA_B11	ETH2_GTX_CLK	PG3	AF3: TIM8_BKIN2 AF4: I2C2_SDA AF6: SAI2_SD_B AF9: FDCAN2_RX AF10: ETH2_RGMII_GTX_CLK AF11: ETH1_MDIO AF12: FMC_A13	-	VDD	
B12	LGA_B12	GND	-	-	-		
B13	LGA_B13	RF_ANT_EXT	-	-	-		External antenna pad. This signal is disconnected inside the module.
B14	LGA_B14	GND	-	-	-		

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
B15	LGA_B15	NC	-	-	-		
B16	LGA_B16	GND	-	-	-		
B17	LGA_B17	NC	-	-	-		
B18	LGA_B18	NC	-	-	-		
B19	LGA_B19	NC	-	-	-		
B20	LGA_B20	NC	-	-	-		
B21	LGA_B21	LTDC_HSYNC	PE1	AF1: LPTIM1_IN2 AF8: UART8_TX AF12: FMC_NBL1	-	VDD	
C1	LGA_C1	VSYS	-	-	-	VSYS	Input power line.
C2	LGA_C2	VSYS	-	-	-	VSYS	Input power line.
C3	LGA_C3	MCA_IO3	-	MCA GPIO/ADC	-	VCC_MCA	
C4	LGA_C4	MCA_IO6/CLKOUT32K	-	MCA GPIO/32KHz output	-	VCC_MCA	
C5	LGA_C5	GND	-	-	-		
C6	LGA_C6	NC	-	-	-	VDD	
C7	LGA_C7	NC	-	-	-	VDD	
C8	LGA_C8	NC	-	-	-	VDD	
C9	LGA_C9	NC	-	-	-	VDD	
C10	LGA_C10	NC	-	-	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
C11	LGA_C11	GND	-	-	-		
C12	LGA_C12	NC	-	-	-		
C13	LGA_C13	GND	-	-	-		
C14	LGA_C14	NC	-	-	-	VDD	
C15	LGA_C15	ETH2_RX_DV	PA12	AF1: TIM1_ETR AF2: SAI2_MCLK_A AF7: USART1_RTS/USART1_DE AF11: ETH2_MII_RX_DV/ETH2_RGMII_RX_CTL/ETH2_RMII_CRS_DV AF12: FMC_A7	-	VDD	
C16	LGA_C16	LPO_32K/PI1	PI1	AF8: SPDIFRX_IN1	RTC_OUT2/RTC_LSCO_TAMP_IN2/TAMP_OUT3_WKUP4	VDD	
C17	LGA_C17	PCM_OUT	-	-	-		Signal connected to the Wireless MAC.
C18	LGA_C18	PCM_SYNC	-	-	-		Signal connected to the Wireless MAC.
C19	LGA_C19	GND	-	-	-		
C20	LGA_C20	PCM_CLK	-	-	-		Signal connected to the Wireless MAC.

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
C21	LGA_C21	LTDC_CLK	PD9	AF0: TRACECLK AF3: DFSDM1_DATIN3 AF10: SDMMC2_CDIR AF12: FMC_D14/FMC_AD14	-	VDD	
D1	LGA_D1	NC	-	-	-		
D2	LGA_D2	GND	-	-	-		
D3	LGA_D3	LDO2_2V8	-	-	-	2V8	Output power line.
D4	LGA_D4	LDO6_1V8	-	-	-	1V8	Output power line.
D5	LGA_D5	GND	-	-	-		
D6	LGA_D6	NC	-	-	-	VDD	
D7	LGA_D7	GND	-	-	-		
D8	LGA_D8	NC	-	-	-		
D9	LGA_D9	LDO3	-	-	-	LDO3	Output power line.
D10	LGA_D10	GND	-	-	-		
D11	LGA_D11	ETH2_REF_CLK	PH11	AF1: SPI5_NSS AF2: TIM5_CH2 AF3: SAI2_SD_A AF5: SPI2_NSS/I2S2_WS AF6: I2C4_SCL AF7: USART6_RX AF9: QUADSPI_BK2_IO0	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF11: ETH2_MII_RX_CLK/ETH2_RGMII_RX_CLK/ETH2_RMII_REF_CLK AF12: FMC_A12			
D12	LGA_D12	VDD_SD	-	-	-	VDD_SD	Output power line.
D13	LGA_D13	3V3_RF_EN/PB7	-	-	-		Signal only available in non-wireless variants.
D14	LGA_D14	NC	-	-	-		
D15	LGA_D15	BT_DEV_WAKE	-	-	-		Signal connected to the Wireless MAC.
D16	LGA_D16	BT_UART_CTS	PD3	AF2: TIM2_CH1 AF3: USART2_CTS/USART2_NSS AF4: DFSDM1_CKOUT AF5: I2C1_SDA AF6: SAI1_D3 AF12: FMC_CLK	-	VDD	Signal only available in non-wireless variants.
D17	LGA_D17	BT_UART_TX	PH12	AF1: USART2_TX AF2: TIM5_CH3 AF3: DFSDM1_CKIN1 AF4: I2C3_SCL AF5: SPI5_MOSI AF6: SAI1_SCK_A AF9: QUADSPI_BK2_IO2	-	VDD	Signal only available in non-wireless variants.

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF10: SAI1_CK2 AF11: ETH1_MII_CRS AF12: FMC_A6			
D18	LGA_D18	BT_UART_RX	PH8	AF0: TRACED9 AF2: TIM5_ETR AF3: USART2_RX AF4: I2C3_SDA AF12: FMC_A8 AF15: HDP2	-	VDD	Signal only available in non-wireless variants.
D19	LGA_D19	BT_UART_RTS	PA1	AF1: TIM2_CH2 AF2: TIM5_CH2 AF3: LPTIM3_OUT AF4: TIM15_CH1N AF6: DFSDM1_CKIN0 AF7: USART2_RTS/USART2_DE AF11: ETH1_MII_RX_CLK/ETH1_RGMII_RX_CLK/ETH1_RMII_REF_CLK	ADC1_INP3 ADC2_INP3	VDD	Signal only available in non-wireless variants.
D20	LGA_D20	PCM_IN	-		-		Signal connected to the Wireless MAC.
D21	LGA_D21	ETH1_TXD0	PG13	AF1: LPTIM1_OUT AF7: USART6_CTS/USART6_NSS AF11: ETH1_MII_TXD0/ETH1_RGMII_TXD0/ETH1_RMII_REF_CLK	ADC2_INP6 ADC2_INN2	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				TXD0			
E1	LGA_E1	NC	-	-	-		PMIC External LDO gate control line.
E2	LGA_E2	WKUP	PF8	AF1: TIM16_CH1N AF2: TIM4_CH3 AF3: TIM8_CH3 AF6: SAI1_SCK_B AF7: USART6_TX AF9: TIM13_CH1 AF10: QUADSPI_BK1_IO0	WKUP1	VDD	
E3	LGA_E3	VDD	-	-	-	VDD	Output power line.
E19	LGA_E19	NC	-	-	-	VDD	
E20	LGA_E20	WL_REG_EN	PD6	AF1: TIM16_CH1N AF2: SAI1_D1 AF6: SAI1_SD_A AF8: UART4_TX	-	VDD	Signal only available in non-wireless variants.
E21	LGA_E21	ETH1_RXD1	PC5	AF3: DFSDM1_DATIN2 AF4: SAI2_D4 AF5: I2S_CKIN AF6: SAI1_D4 AF7: USART2_CTS/USART2_NSS AF9: SPDIFRX_IN3 AF11: ETH1_MII_RXD1/ETH1_RGMII_RXD1/ETH1_RMII_RXD1	ADC1_INP10 ADC2_INP10	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
F1	LGA_F1	GND	-	-	-		
F2	LGA_F2	GND	-	-	-		
F3	LGA_F3	VSYS	-	-	-	VSYS	Input power line.
F19	LGA_F19	WL_HOST_WAKE	-	-	-		Signal connected to the Wireless MAC.
F20	LGA_F20	NC	-	-	-	VDD	
F21	LGA_F21	ETH1_REF_CLK	PD7	AF0: MCO1 AF3: USART2_CK AF4: I2C2_SCL AF5: I2C3_SDA AF9: SPDIFRX_IN0 AF10: ETH1_MII_RX_CLK/ETH1_RGMII_RX_CLK/ETH1_RMII_REF_CLK AF11: QUADSPI_BK1_IO2 AF12: FMC_NE1	-	VDD	
G1	LGA_G1	VSYS	-	-	-	VSYS	Input power line.
G2	LGA_G2	VSYS	-	-	-	VSYS	Input power line.
G3	LGA_G3	VSYS	-	-	-	VSYS	Input power line.
G19	LGA_G19	BT_REG_EN	PD13	AF1: LPTIM2_ETR AF2: TIM4_CH2 AF3: TIM8_CH2 AF4: SAI1_CK1 AF6: SAI1_MCLK_A	-	VDD	Signal only available in non-wireless variants.

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF7: USART1_RX AF9: QUADSPI_BK1_IO3 AF11: QUADSPI_BK2_IO2 AF12: FMC_A18			
G20	LGA_G20	GND	-	-	-		
G21	LGA_G21	ETH1_TX_EN	PB11	AF1: TIM2_CH4 AF3: LPTIM1_OUT AF4: I2C5_SMBA AF7: USART3_RX AF11: ETH1_MII_TX_EN/ETH1_RGMII_TX_CTL/ETH1_RMII_TX_EN	-	VDD	
H1	LGA_H1	VSYS2	-	-	-	VSYS2	Input power line.
H2	LGA_H2	VSYS2	-	-	-	VSYS2	Input power line.
H3	LGA_H3	VSYS2	-	-	-	VSYS2	Input power line.
H19	LGA_H19	PI2	PI2	AF8: SPDIFRX_IN2	TAMP_IN3/TAMP_OUT4_WKUP5	VDD	
H20	LGA_H20	BT_HOST_WAKE	-	-	-		Signal connected to the Wireless MAC.
H21	LGA_H21	ETH1_TXD1	PG14	AF1: LPTIM1_ETR AF6: SAI2_D1 AF7: USART6_TX AF10: SAI2_SD_A	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF11: ETH1_MII_TXD1/ETH1_RGMII_TXD1/ETH1_RMII_TXD1			
J1	LGA_J1	GND	-	-	-		
J2	LGA_J2	GND	-	-	-		
J3	LGA_J3	VSYS2	-	-	-		Input power line.
J19	LGA_J19	NC	-	-	-	VDD	
J20	LGA_J20	NC	-	-	-	VDD	
J21	LGA_J21	ETH1_RX_ER	PI3	AF8: SPDIFRX_IN3 AF11: ETH1_MII_RX_ER	TAMP_IN4/TAMP_OUT5 WKUP2	VDD	
K1	LGA_K1	VDD	-	-	-	VDD	Output power line.
K2	LGA_K2	VDD	-	-	-	VDD	Output power line.
K3	LGA_K3	VDD	-	-	-	VDD	Output power line.
K19	LGA_K19	WLAN_SD_CLK	PE3	AF0: TRACED11 AF2: SAI2_D4 AF4: TIM15_BKIN AF5: SPI4_MISO/I2S4_SDI AF8: USART3_RTS/USART3_DE AF9: FDCAN1_RX AF10: SDMMC2_CK	-	VDD	Signal only available in non-wireless variants.
K20	LGA_K20	WLAN_SD_D2	PB3	AF0: TRACED2 AF1: TIM2_CH2	-	VDD	47K pull-up on module connected to VDD.

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF4: SAI2_CK1 AF5: SPI4_NSS/I2S4_WS AF8: SDMMC1_D123DIR AF10: SDMMC2_D2 AF12: SAI2_MCLK_A AF13: UART7_RX			Signal only available in non-wireless variants.
K21	LGA_K21	ETH1_RX_DV	PA7	AF1: TIM1_CH1N AF2: TIM3_CH2 AF3: TIM8_CH1N AF4: SAI2_D1 AF5: SPI1_SCK/I2S1_CK AF7: USART1_CTS/USART1_NSS AF9: TIM14_CH1 AF11: ETH1_MII_RX_DV/ETH1_RGMII_RX_CTL/ETH1_RMII CRS_DV AF12: SAI2_SD_A	ADC1_INP16	VDD	
L1	LGA_L1	NC	-	-	-	VDD	
L2	LGA_L2	GND	-	-	-		
L3	LGA_L3	VREF+	VREF+	-	-		
L19	LGA_L19	WLAN_SD_CMD	PG6	AF0: TRACED3 AF1: TIM17_BKIN AF2: TIM5_CH4 AF3: SAI2_D1	-	VDD	47K pull-up on module connected to VDD. Signal only available in non-wireless variants.

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF4: USART1_RX AF6: SAI2_SD_A AF10: SDMMC2_CMD AF15: HDP3			
L20	LGA_L20	WLAN_SD_D1	PB15	AF0: RTC_REFIN AF1: TIM1_CH3N AF2: TIM12_CH2 AF3: TIM8_CH3N AF4: SAI2_D2 AF5: SPI4_MOSI/I2S4_SDO AF6: DFSDM1_CKIN2 AF7: UART7_CTS AF8: SDMMC1_CKIN AF10: SDMMC2_D1 AF12: SAI2_FS_A	-	VDD	47K pull-up on module connected to VDD. Signal only available in non-wireless variants.
L21	LGA_L21	ETH1_RXD0	PC4	AF2: TIM3_ETR AF3: DFSDM1_CKIN2 AF4: SAI1_D3 AF5: I2S1_MCK AF8: UART5_RTS/UART5_DE AF9: SPDIFRX_IN2 AF11: ETH1_MII_RXD0/ETH1_RGMII_RXD0/ETH1_RMII_RXD0 AF12: SAI2_D3	ADC1_INP4 ADC2_INP4	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
M1	LGA_M1	NC	-		-	VDD	
M2	LGA_M2	ETH2_MDIO	PB2	AF1: RTC_OUT2 AF2: SAI1_D1 AF5: I2S_CKIN AF6: SAI1_SD_A AF8: UART4_RX AF9: QUADSPI_BK1_NCS AF11: ETH2_MDIO AF12: FMC_A6	TAMP_IN7	VDD	
M3	LGA_M3	ETH2_MDC	PG5	AF1: TIM17_CH1 AF10: ETH2_MDC AF12: FMC_A15	-	VDD	
M19	LGA_M19	WLAN_SD_D0	PB14	AF0: TRACED0 AF1: TIM1_CH2N AF2: TIM12_CH1 AF3: TIM8_CH2N AF4: USART1_TX AF10: SDMMC2_D0 AF11: SDMMC1_D4	-	VDD	47K pull-up on module connected to VDD. Signal only available in non-wireless variants.
M20	LGA_M20	WLAN_SD_D3	PB4	AF0: TRACED14 AF1: TIM16_BKIN AF2: TIM3_CH1 AF4: SAI2_CK2 AF5: SPI4_SCK/I2S4_CK AF7: USART3_CK AF10: SDMMC2_D3 AF12: SAI2_SCK_A	-	VDD	47K pull-up on module connected to VDD. Signal only available in non-wireless variants.
M21	LGA_M21	UART8_CTS	PG10	AF5: SPI5_SCK AF6: SAI1_SD_B	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF8: UART8_CTS AF9: FDCAN1_TX AF10: QUADSPI_BK2_IO1 AF12: FMC_NE3			
N1	LGA_N1	NC	-	-	-		
N2	LGA_N2	FDCAN2_RX	PB5	AF0: TRACED4 AF1: TIM17_BKIN AF2: TIM3_CH2 AF5: SPI2_MISO/I2S2_SD1 AF6: I2C4_SMBAL AF8: SDMMC1_CKIN AF9: FDCAN2_RX AF11: UART5_RX	-	VDD	
N3	LGA_N3	GND	-	-	-		
N19	LGA_N19	SPI4_MOSI	PE11	AF1: TIM1_CH2 AF2: USART2_CTS/USART2_NSS AF4: SAI1_D2 AF5: SPI4_MOSI/I2S4_SDO AF6: SAI1_FS_A AF7: USART6_CK AF10: ETH2_MII_TX_ER AF11: ETH1_MII_TX_ER AF12: FMC_D8/FMC_AD8	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
N20	LGA_N20	SPI4_MISO	PE13	AF1: TIM1_CH3 AF4: I2C5_SDA AF5: SPI4_MISO/I2S4_SD1 AF12: FMC_D10/FMC_AD10	-	VDD	
N21	LGA_N21	UART8_RTS	PE14	AF1: TIM1_BKIN AF4: SAI1_D4 AF8: UART8_RTS/UART8_DE AF9: QUADSPI_BK1_NCS AF10: QUADSPI_BK2_IO2 AF12: FMC_D11/FMC_AD11	TAMP_IN6	VDD	
P1	LGA_P1	NRST	NRST	-	-	VDD	Reset line of the CPU. Recommendation: leave this pin floating.
P2	LGA_P2	VDD	-	-	-	VDD	Output power line.
P3	LGA_P3	GND	-	-	-		
P19	LGA_P19	USART3_RTS	PG8	AF1: TIM2_CH1 AF3: TIM8_ETR AF5: SPI5_MISO AF6: SAI1_MCLK_B AF8: USART3_RTS/USART3_DE AF9: SPDIFRX_IN2 AF10: QUADSPI_BK2_IO2	TAMP_IN4	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF11: QUADSPI_BK1_IO3 AF12: FMC_NE2 AF13: ETH2_CLK			
P20	LGA_P20	USART3_CTS	PG12	AF1: LPTIM1_IN1 AF4: SAI2_SCK_A AF6: SAI2_CK2 AF7: USART6_RTS/USART6_DE AF8: USART3_CTS AF10: ETH2_PHY_INTN AF11: ETH1_PHY_INTN AF12: ETH2_MII_RX_DV/ETH2_RGMII_RX_CTL/ETH2_RMII_CRS_DV	-	VDD	
P21	LGA_P21	GND	-	-	-		
R1	LGA_R1	I2S1_WS	PA4	AF2: TIM5_ETR AF3: USART2_CK AF4: SAI1_SCK_B AF5: SPI1_NSS/I2S1_WS AF6: DFSDM1_CKIN1 AF10: ETH1_PPS_OUT AF11: ETH2_PPS_OUT	ADC1_INP14	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF12: SAI1_SCK_A			
R2	LGA_R2	FDCAN2_TX	PB13	AF0: TRACECLK AF1: TIM1_CH1N AF4: LPTIM2_OUT AF5: SPI2_NSS/I2S2_WS AF6: I2C4_SCL AF8: SDMMC1_D123DIR AF9: FDCAN2_TX AF11: UART5_TX	-	VDD	
R3	LGA_R3	GND	-	-	-		
R19	LGA_R19	USART3_RX	PG4	AF0: TRACED1 AF1: TIM1_BKIN2 AF4: DFSDM1_CKIN3 AF8: USART3_RX AF10: SDMMC2_D123DIR AF12: FMC_A14 AF15: HDP1	-	VDD	
R20	LGA_R20	USART3_TX	PD8	AF3: USART2_TX AF5: I2S4_WS AF7: USART3_TX AF8: UART4_RX	-	VDD	
R21	LGA_R21	UART8_RX	PE0	AF8: UART8_RX AF9: FDCAN2_RX AF12: FMC_A11	-	VDD	
T1	LGA_T1	I2S1_CK	PC3	AF2: SAI1_CK1 AF3: DFSDM1_	ADC1_INP13 ADC1_INN12	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				CKOUT AF5: SPI1_MISO/I2S1_SD AF6: SPI1_SCK/I2S1_CK AF8: UART5_CTS AF10: SAI1_MCLK_A AF11: ETH1_MII_TX_CLK AF12: ETH2_MII_TX_CLK	TAMP_IN5		
T2	LGA_T2	NC	-	-	-		
T3	LGA_T3	NC	-	-	-		
T19	LGA_T19	ETH2_RXD3	PA8	AF0: MCO1 AF2: SAI2_MCLK_A AF3: TIM8_BKIN2 AF4: I2C4_SDA AF5: SPI5_MISO AF6: SAI2_CK1 AF7: USART1_CK AF8: SPI2_MOSI/I2S2_SDO AF10: OTG_HS_SOF AF11: ETH2_MII_RXD3/ETH2_RGMII_RXD3 AF12: FMC_A21	-	VDD	
T20	LGA_T20	NC	-	-	-	VDD	
T21	LGA_T21	UART8_TX	PE4	AF1: SPI5_MISO AF2: SAI1_D2	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF3: DFSDM1_DATIN3 AF4: TIM15_CH1N AF5: I2S_CKIN AF6: SAI1_FS_A AF7: UART7_RTS/UART7_DE AF8: UART8_TX AF9: QUADSPI_BK2_NCS AF10: FMC_NCE2 AF12: FMC_A25			
U1	LGA_U1	SDMMC1_D1	PC9	AF0: TRACED1 AF2: TIM3_CH4 AF3: TIM8_CH4 AF7: USART3_RTS AF8: UART5_CTS AF9: FDCAN1_TX AF12: SDMMC1_D1	-	VDD	
U2	LGA_U2	NC	-	-	-	VDD	
U3	LGA_U3	NC	-	-	-	VDD	
U19	LGA_U19	PA5	PA5	AF1: TIM2_CH1/TIM2_ETR AF2: USART2_CK AF3: TIM8_CH1N AF4: SAI1_D1 AF5: SPI1_NSS/I2S1_WS AF6: SAI1_SD_A AF10: ETH1_PPS_OUT	ADC1_INP2	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF11: ETH2_PPS_OUT			
U20	LGA_U20	LTDC_R3	PB10	AF1: TIM2_CH3 AF3: LPTIM2_IN1 AF4: I2C5_SMBA AF5: SPI4_NSS/I2S4_WS AF6: SPI2_SCK/I2S2_CK AF7: USART3_TX	-	VDD	
U21	LGA_U21	JTRST	JTRST	-	-		
V1	LGA_V1	SDMMC1_CMD	PD2	AF0: TRACED4 AF2: TIM3_ETR AF4: I2C1_SMBA AF5: SPI3_NSS/I2S3_WS AF6: SAI2_D1 AF7: USART3_RX AF12: SDMMC1_CMD	-	VDD	
V2	LGA_V2	GND	-	-	-		
V3	LGA_V3	BOOT0	BOOT0	-	-	VDD	100K pull-up resistor.
V4	LGA_V4	GND	-	-	-		
V5	LGA_V5	ETH2_RXD0	PF4	AF3: USART2_RX AF11: ETH2_MII_RXD0/ETH2_RGMII_RXD0/ETH2_RMII_RXD0 AF12: FMC_A4	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
V6	LGA_V6	GND	-	-	-		
V7	LGA_V7	NC	-	-	-	VDD	
V8	LGA_V8	LTDC_R2	PG7	AF0: TRACED8 AF1: TIM1_ETR AF5: SPI3_ MISO/I2S3_SD1 AF8: UART7_CTS AF10: SDMMC2_ CKIN	-	VDD	
V9	LGA_V9	LTDC_R5	PF5	AF0: TRACED12 AF4: DFSDM1_ CKIN0 AF5: I2C1_SMBA AF12: FMC_A5	-	VDD	
V10	LGA_V10	NC	-	-	-	VDD	
V11	LGA_V11	GND	-	-	-		
V12	LGA_V12	SPI4_SCK	PE12	AF1: TIM1_CH3N AF5: SPI4_ SCK/I2S4_CK AF8: UART8_ RTS/UART8_DE AF12: FMC_ D9/FMC_AD9 AF15: HDP4	-	VDD	
V13	LGA_V13	LTDC_G7	PA15	AF0: TRACED5 AF1: TIM2_CH1 AF5: I2S4_MCK AF7: UART4_ RTS/UART4_DE	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF8: UART4_RX AF12: FMC_A9 AF15: HDP5			
V14	LGA_V14	ETH2_RXD1	PE2	AF0: TRACECLK AF1: TIM2_ETR AF4: I2C4_SCL AF5: SPI5_MOSI AF6: SAI1_FS_B AF7: USART6_ RTS/USART6_DE AF9: SPDIFRX_IN1 AF10: ETH2_MII_ RXD1/ETH2_RGMII_ RXD1/ETH2_RMII_ RXD1 AF12: FMC_A23	-	VDD	
V15	LGA_V15	ETH2_RXD2	PH6	AF2: TIM12_CH1 AF3: USART2_CK AF4: I2C5_SDA AF5: SPI2_ SCK/I2S2_CK AF9: QUADSPI_ BK1_IO2 AF10: ETH1_PHY_ INTN AF11: ETH1_MII_ RX_ER AF12: ETH2_MII_ RXD2/ETH2_RGMII_ RXD2 AF13: QUADSPI_ BK1_NCS	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
V16	LGA_V16	GND	-	-	-		
V17	LGA_V17	ETH1_CLK125	PF12	AF5: SPI1_NSS/I2S1_WS AF6: SAI1_SD_A AF8: UART4_TX AF10: ETH1_MII_TX_ER AF11: ETH1_RGMII_CLK125	ADC1_INP6 ADC1_INN2	VDD	
V18	LGA_V18	ETH1_GTX_CLK	PC1	AF3: DFSDM1_DATIN0 AF6: SAI1_D3 AF10: ETH1_MII_RX_DV/ETH1_RMII_CRS_DV AF11: ETH1_RGMII_GTX_CLK	ADC2_INP2	VDD	
V19	LGA_V19	PG0	PG0	AF9: FDCAN2_TX AF12: FMC_A10	-	VDD	
V20	LGA_V20	PA11	PA11	AF1: TIM1_CH4 AF3: I2C5_SCL AF5: SPI2_NSS/I2S2_WS AF7: USART1_CTS/USART1_NSS AF10: ETH2_MII_RXD1/ETH2_RGMII_RXD1/ETH2_RMII_RXD1 AF11: ETH1_CLK AF13: ETH2_CLK	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
V21	LGA_V21	JTDI	JTDI	-	-		
W1	LGA_W1	PA13	PA13	AF0: DBTRGO AF1: DBTRGI AF2: MCO1 AF8: UART4_TX	BOOTFAILN	VDD	
W2	LGA_W2	SDMMC1_D4	PH10	AF0: TRACED0 AF2: TIM5_CH1 AF3: SAI2_D3 AF4: DFSDM1_DATIN2 AF5: I2S3_MCK AF6: SPI2_MOSI/I2S2_SDO AF7: USART3_CTS/USART3_NSS AF8: SDMMC1_D4 AF15: HDP0	-	VDD	
W3	LGA_W3	SDMMC1_D6	PC6	AF0: TRACED2 AF2: TIM3_CH1 AF3: TIM8_CH1 AF4: DFSDM1_DATINO AF5: I2S3_MCK AF7: USART6_TX AF8: SDMMC1_D6 AF9: SDMMC2_DODIR AF10: SDMMC2_D6 AF12: FMC_A19 AF15: HDP2	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
W4	LGA_W4	NC	-	-	-	VDD	
W5	LGA_W5	SDMMC1_D7	PC7	AF0: TRACED4 AF2: TIM3_CH2 AF3: TIM8_CH2 AF6: I2S2_MCK AF7: USART6_RX AF8: USART3_CTS AF9: SDMMC2_CDIR AF10: SDMMC2_D7 AF12: SDMMC1_D7 AF15: HDP4	-	VDD	
W6	LGA_W6	GND	-	-	-		
W7	LGA_W7	NC	-	-	-		
W8	LGA_W8	PMIC_PONKEY_N	-	-	-	VDD	PMIC Power ON key. Recommendation: leave this pin floating.
W9	LGA_W9	NC	-	-	-	VDD	
W10	LGA_W10	LTDC_R6	PF0	AF0: TRACED13 AF3: DFSDM1_CKOUT AF7: USART3_CK AF10: SDMMC2_D4 AF12: FMC_A0	-	VDD	
W11	LGA_W11	GND	-	-	-		
W12	LGA_W12	GND	-	-	-		
W13	LGA_W13	ETH2_RX_ER	PF11	AF1: USART2_TX AF2: SAI1_D2	ADC1_INP8 ADC1_INN4 ADC2_INP8	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF3: DFSDM1_CKIN3 AF6: SAI1_FS_A AF12: ETH2_MII_RX_ER	ADC2_INN4		
W14	LGA_W14	PWR_ON	PWR_ON	-	-		CPU core supply enable output. Internally connected to the PMIC. Leave this pin unconnected unless otherwise noted.
W15	LGA_W15	ETH2_CLK125	PH2	AF1: LPTIM1_IN2 AF8: UART7_TX AF9: QUADSPI_BK2_IO0 AF10: ETH2_MII CRS AF11: ETH1_MII CRS AF12: FMC_NE4 AF13: ETH2_RGMII_CLK125	-	VDD	
W16	LGA_W16	GND	-	-	-		
W17	LGA_W17	ETH1_RXD2	PB0	AF0: DBTRGI AF1: TIM1_CH2N AF2: TIM3_CH3 AF3: TIM8_CH2N AF4: USART1_RX AF5: I2S1_MCK AF6: SAI2_FS_A AF7: USART1_CK AF8: UART4_CTS	ADC1_INP9 ADC1_INN5 ADC2_INP9 ADC2_INN5	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF10: SAI2_D2 AF11: ETH1_MII_RXD2/ETH1_RGMII_RXD2			
W18	LGA_W18	ETH1_TXD2	PC2	AF1: SPI5_NSS AF5: SPI1_NSS/I2S1_WS AF6: SAI2_MCLK_A AF7: USART1_RTS/USART1_DE AF10: SAI2_CK1 AF11: ETH1_MII_TXD2/ETH1_RGMII_TXD2	ADC1_INP15	VDD	
W19	LGA_W19	ETH1_RXD3	PB1	AF1: TIM1_CH3N AF2: TIM3_CH4 AF3: TIM8_CH3N AF5: SPI1_SCK/I2S1_CK AF6: DFSDM1_DATIN1 AF7: UART4_RX AF11: ETH1_MII_RXD3/ETH1_RGMII_RXD3	ADC1_INP5 ADC2_INP5	VDD	
W20	LGA_W20	ETH1_TXD3	PE5	AF2: SAI2_SCK_B AF3: TIM8_CH3 AF4: TIM15_CH1 AF8: UART4_RX AF10: ETH1_MII_TXD3/ETH1_RGMII_	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				TXD3 AF12: FMC_NE1			
W21	LGA_W21	JTCK-SWCLK	JTCK-SWCLK	-	-		
Y1	LGA_Y1	BOOT1	BOOT1	-	-	VDD	100K pull-up resistor.
Y2	LGA_Y2	SDMMC1_D5	PB12	AF0: TRACED10 AF4: I2C2_SMBA AF6: DFSDM1_DATIN1 AF7: UART7_RTS/UART7_DE AF8: USART3_RX AF11: USART5_RX AF12: SDMMC1_D5	-	VDD	
Y3	LGA_Y3	NC	-	-	-	VDD	
Y4	LGA_Y4	I2S1_MCK	PC0	AF2: SAI1_SCK_A AF4: SAI1_CK2 AF5: I2S1_MCK AF6: SPI1_MOSI/I2S1_SDO AF7: USART1_TX	ADC1_INP0 ADC1_INN1 ADC2_INP0 ADC2_INN1 TAMP_IN3	VDD	
Y5	LGA_Y5	NC	-	-	-	VDD	
Y6	LGA_Y6	NC	-	-	-	VDD	
Y7	LGA_Y7	I2C3_SCL	PB8	AF1: TIM16_CH1 AF2: TIM4_CH3 AF4: I2C1_SCL AF5: I2C3_SCL AF6: DFSDM1_DATIN1	-	VDD	2.2K pull-up on module connected to VDD.

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF8: UART4_RX AF10: SAI1_D1 AF12: FMC_D13/FMC_AD13			
Y8	LGA_Y8	I2C3_SDA	PH14	AF3: DFSDM1_DATIN2 AF4: I2C3_SDA AF8: UART4_RX	-	VDD	2.2K pull-up on module connected to VDD.
Y9	LGA_Y9	SPI4_NSS	PD10	AF0: RTC_REFIN AF4: I2C5_SMBA AF5: SPI4_NSS/I2S4_WS AF7: USART3_CK AF12: FMC_D15/FMC_AD15	-	VDD	
Y10	LGA_Y10	GND	-	-	-		
Y11	LGA_Y11	VBUS_OTG	-	-	-		Output power line.
Y12	LGA_Y12	NC	-	-	-	VDD	
Y13	LGA_Y13	I2C2_SCL	PF2	AF0: TRACED1 AF4: I2C2_SCL AF6: DFSDM1_CKIN1 AF7: USART6_CK AF9: SDMMC2_D0DIR AF11: SDMMC1_D0DIR AF12: FMC_A2	-	VDD	
Y14	LGA_Y14	I2C2_SDA	PF1	PF1: TRACED7	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF4: I2C2_SDA AF5: SPI3_MOSI/I2S3_SDO AF12: FMC_A1 AF15: HDP7			
Y15	LGA_Y15	VBUS_SW	-	-	-		Output power line.
Y16	LGA_Y16	VBUS_SW	-	-	-		Output power line.
Y17	LGA_Y17	NC	-	-	-	VDD	
Y18	LGA_Y18	NC	-	-	-		
Y19	LGA_Y19	PA14	PA14	AF0: DBTRGO AF1: DBTRGI AF2: MCO2 AF10: OTG_HS_SOF	-	VDD	
Y20	LGA_Y20	NC	-	-	-	VDD	
Y21	LGA_Y21	JTDO-TRACESWO	JTDO-TRACESWO	-	-		
AA1	LGA_AA1	GND	-	-	-		
AA2	LGA_AA2	SDMMC1_D0	PC8	AF0: TRACED0 AF2: TIM3_CH3 AF3: TIM8_CH3 AF5: SPI3_MISO/I2S3_SDI AF7: USART6_CK AF8: USART3_CTS AF10: SAI2_FS_B AF11: UART5_RTS/UART5_DE	-	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				AF12: SDMMC1_D0			
AA3	LGA_AA3	SDMMC1_CLK	PC12	AF0: TRACECLK AF8: UART7_TX AF10: SAI2_SD_B AF12: SDMMC1_CK	-	VDD	
AA4	LGA_AA4	SDMMC1_D2	PC10	AF0: TRACED2 AF5: I2C1_SCL AF6: SPI3_SCK/I2S3_CK AF7: USART3_TX AF10: SAI2_MCLK_B AF12: SDMMC1_D2	-	VDD	
AA5	LGA_AA5	SDMMC1_D3	PC11	AF0: TRACED3 AF4: I2C1_SDA AF6: SPI3_MOSI/I2S3_SDO AF7: USART3_CK AF8: UART5_RX AF10: SAI2_SCK_B AF12: SDMMC1_D3	-	VDD	
AA6	LGA_AA6	UART5_TX	PA0	AF1: TIM2_CH1 AF2: TIM5_CH1 AF3: TIM8_ETR AF4: TIM15_BKIN AF6: SAI1_SD_B AF8: UART5_TX AF11: ETH1_MII_CRS AF12: ETH2_MII_CRS	ADC1_INP7 ADC1_INN3 ADC2_INP7 ADC2_INN3	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
AA7	LGA_AA7	UART5_RX	PF13	AF1: TIM2_ETR AF2: SAI1_MCLK_B AF6: DFSDM1_DATIN3 AF7: USART2_TX AF8: UART5_RX	ADC1_INP11 ADC1_INN10 ADC2_INP11 ADC2_INN10	VDD	
AA8	LGA_AA8	USB2_D_P	USB_DP2	-	USBH_HS_DP2 OTG_HS_DP		
AA9	LGA_AA9	USB2_D_N	USB_DM2	-	USBH_HS_DM2 OTG_HS_DM		
AA10	LGA_AA10	GND	-	-	-		
AA11	LGA_AA11	OTG_VBUS	PI7	-	OTG_HS_VBUS		Input power line.
AA12	LGA_AA12	I2S1_SDI	PA6	AF1: TIM1_BKIN AF2: TIM3_CH1 AF3: TIM8_BKIN AF4: SAI2_CK2 AF5: SPI1_MISO/I2S1_SDI AF7: USART1_CK AF8: UART4_RTS/UART4_DE AF9: TIM13_CH1 AF12: SAI2_SCK_A	ADC1_INP17 ADC1_INN16 TAMP_IN2	VDD	
AA13	LGA_AA13	USB_OTG_ID	PA10	AF1: TIM1_CH3	OTG_HS_ID		
AA14	LGA_AA14	I2S1_SDO	PA3	AF1: TIM2_CH4 AF2: TIM5_CH4 AF3: LPTIM5_OUT AF4: TIM15_CH2 AF5: SPI1_	ADC1_INP12 ADC1_INN11 PVD_IN WKUP6	VDD	

LGA pad	ConnectCore MP13 pad	ConnectCore MP13 signal name	STM32MP135 pad name	Alternate functions	Additional functions	Power group	Comments
				MOSI/I2S1_SDO AF6: SAI1_FS_B AF7: USART2_RX AF11: ETH1_MII_COL AF12: ETH2_MII_COL			
AA15	LGA_AA15	BOOT2	BOOT2	-	-		
AA16	LGA_AA16	JTMS-SWDIO	JTMS-SWDIO	-	-		
AA17	LGA_AA17	USB1_D_P	USB_DP1	-	USBH_HS_DP1		
AA18	LGA_AA18	USB1_D_N	USB_DM1	-	USBH_HS_DM1		
AA19	LGA_AA19	ETH1_MDC	PG2	AF1: MCO2 AF3: TIM8_BKIN AF10: SAI2_MCLK_B AF11: ETH1_MDC	-	VDD	
AA20	LGA_AA20	ETH1_MDIO	PA2	AF1: TIM2_CH3 AF2: TIM5_CH3 AF3: LPTIM4_OUT AF4: TIM15_CH1 AF7: USART2_TX AF11: ETH1_MDIO	ADC1_INP1 ADC2_INP1	VDD	
AA21	LGA_AA21	GND	-	-	-		

Module specifications

The following sections describe the specifications for the ConnectCore MP13 SOM.

Mechanical specifications	74
Environmental specifications	75
Socket options	75

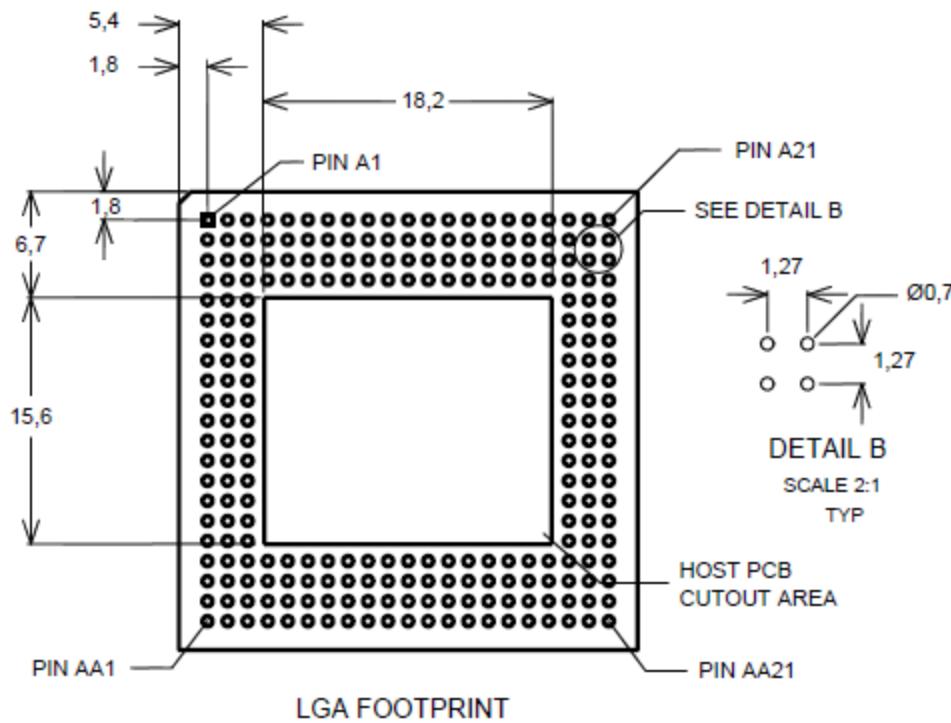
Mechanical specifications

This section provides mechanical dimensions and host PCB footprint guidance for the Digi SMTplus® form factor of the ConnectCore MP13 module.

Host PCB footprint and cutout

Note Host PCBs must have a cutout to accommodate the components on the bottom side of the module.

Digi SMTplus® LGA mounting



Label

The MAC address and serial number of the SOM are encoded in the data matrix on the SOM label.

Note See the ConnectCore MP13 product page for mechanical design documents, drawings, and other resources.

Environmental specifications

Operating temperature: -40 to 85 C.



CAUTION! Your final product may require additional thermal management such as passive (heatsink/spreader) or active (airflow) cooling to achieve the maximum operating temperature without exceeding the processor junction temp limit.

Socket options

For testing, prototyping, and other primarily development-related purposes, Digi International and E-tec Interconnect AG have developed sockets allowing the easy insertion and removal of modules in a carrier board design.

All drawings, user instructions, schematics and PCB footprints are posted on the ConnectCore MP13 technical support website.

Note The ConnectCore MP1 Development Board (Digi P/N CC-WMP137-KIT) has been designed to support a RF-LPF246-129M-21AAEW55L-CCMP1 socket, and can be used as a reference design.

All sockets are sold and built by [E-tec Interconnect AG](#). The table below provides an overview of the available part numbers.

Socket model	E-tec part number
ConnectCore MP13	RF-LPF246-129M-21AAEW55L-CCMP1

Note Please direct all socket-related purchase inquiries to E-tec Interconnect AG (info@e-tec.com).

Regulatory information and certifications

Note The ConnectCore MP13 module complies with Part 15 of the United States FCC rules and regulations.

United States FCC	77
Europe and UK	81
Canada (IC)	84
Japan	86

United States FCC

The ConnectCore MP13 module complies with Part 15 of the FCC rules and regulations. Compliance with the labeling requirements, FCC notices and antenna usage guidelines is required. To fulfill FCC Certification, the OEM must comply with the following regulations:

The system integrator must ensure that the text on top side of the module is placed on the outside of the final product.

The ConnectCore MP13 module may only be used with approved antennas. (See [FCC-approved antennas](#).)

Labeling requirements



WARNING! The Original Equipment Manufacturer (OEM) must ensure that FCC labeling requirements are met. This includes a clearly visible label on the outside of the final product enclosure that displays the contents shown below. Required FCC Label for OEM products containing the ConnectCore MP13 module.

Contains FCC ID: MCQ-CCMP1

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Maximum power and frequency specifications (FCC)

RF band	Peak antenna gain	Technology	Channel bandwidth	Channel number (Center frequency, MHz)
2.4 GHz	2.5 dBi	BT + EDR Bluetooth LE	1	79 non-overlapping channels: 0 (2400) to 78 (2480)
			2	40 non-overlapping channels: 0 (2402) to 39 (2480)
		WLAN	20	1(2412), 2(2417), 3(2422), 4(2427), 5(2432), 6 (2437), 7(2442), 8(2447), 9 (2452), 10(2457), 11 (2462)
			40	3(2422), 4(2427), 5(2432), 6(2437), 7(2442), 8 (2447), 9(2452)
5 GHz	4.6 dBi	WLAN	20	36(5180), 40(5200), 44(5220), 48(5240), 52 (5260), 56(5280), 60(5300), 64 (5320), 100(5500), 104(5520), 108(5540), 112(5560), 116(5580), 120 (5600), 124(5620), 128(5640), 132(5660), 136 (5680), 140(5700), 149 (5745), 153(5765), 157 (5785), 161(5805), 165(5825)
			40	38(5190), 46(5230), 54(5270), 62(5310), 102 (5510), 110(5550), 118(5590), 126(5630), 134

RF band	Peak antenna gain	Technology	Channel bandwidth	Channel number (Center frequency, MHz)
				(5670), 151(5755), 159(5795)
			80	42(5210), 58(5290), 106(5530), 122(5610), 155(5775)

FCC notices

IMPORTANT: The ConnectCore MP13 module has been certified by the FCC for use with other products without any further certification (as per FCC section 2.1091). Modifications not expressly approved by Digi could void the user's authority to operate the equipment.

IMPORTANT: OEMs must test final product to comply with unintentional radiators (FCC section 15.107 & 15.109) before declaring compliance of their final product to Part 15 of the FCC Rules.

IMPORTANT: The ConnectCore MP13 module has been certified for remote and base radio applications. If the module will be used for portable applications, the device must undergo SAR testing. This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures: Re-orient or relocate the receiving antenna, Increase the separation between the equipment and receiver, Connect equipment and receiver to outlets on different circuits, or Consult the dealer or an experienced radio/TV technician for help.

IMPORTANT: This module has been tested and found to comply with the following requirements for Modular Approval.

Part 15.247 - Operation within the bands 902-928 MHz, 2400-2483.5 MHz, and 5725-5850 MHz.

Part 15.407 – General technical requirements.

FCC-approved antennas

The ConnectCore MP13 module can be installed utilizing antennas and cables constructed with non-standard connectors (RPSMA, RPTNC, and so on).

The modules are FCC approved for fixed base station and mobile applications for the channels indicated in the tables below. If the antenna is mounted at least 20 cm (8 in) from nearby persons, the application is considered a mobile application. Antennas not listed in the table must be tested to comply with FCC Section 15.203 (Unique Antenna Connectors) and Section 15.247 (Emissions).

The following table shows the antenna that was used to certify the ConnectCore MP13 wireless module. This antenna can be replaced by others, however further certification testing is required. The number of tests to be carried out can be decreased by using an antenna of the same type, i.e. dualband omnidirectional dipole, showing lower peak gain. In such case, only a spot check may be required by the certification laboratories to keep current certifications valid according to FCC regulations. If replacing by an antenna with higher gain, complete radiated tests according to FCC regulations are required by the certification laboratories.

Antenna used to certify the ConnectCore MP13 wireless module

Antenna Type	Supplier	Antenna part no.	Freq. (MHz)	Peak antenna gain (dBi)	Directional gain (dBi)
Dipole	Linx Technologies Inc.	ANT-DB1-RAF-RPS	2402-2480	2.5	5.51
			5150-5250	4.6	7.61
			5250-5350	4.6	7.61
			5470-5725	4.6	7.61
			5725-5850	4.6	7.61
Dipole	KYOCERA	X9001091-W3DRMB	2402-2480	1.8	-
			5150-5250	4.0	-
			5250-5350	4.0	-
			5470-5725	4.0	-
			5725-5850	4.0	-
Dipole	TAOGLAS	GW.48.A151	2402-2480	3.42	6.43
			5150-5250	4.56	7.57
			5250-5350	4.56	7.57
			5470-5725	4.56	7.57
			5725-5850	4.56	7.57
PCB	ETHERTRONICS	1001932	2402-2480	2.5	5.51
			5150-5250	5	8.01
			5250-	5	8.01

Antenna Type	Supplier	Antenna part no.	Freq. (MHz)	Peak antenna gain (dBi)	Directional gain (dBi)
			5350		
			5470-5725	5	8.01
			5725-5850	5	8.01
PCB	YAGEO	ANTX100P001B24553	2402-2480	4.6	7.61
			5150-5250	4.9	7.91
			5250-5350	3.9	6.91
			5470-5725	5.1	8.11
			5725-5850	5.1	8.11
PCB	KYOCERA	W3P35x8W04-U100D3B0A	2402-2480	2.3	-
			5150-5250	5	-
			5250-5350	5	-
			5470-5725	5	-
			5725-5850	5	-
PCB	TAOGLAS	FXP830.07.0100C *	2402-2480	3.32	6.33
			5150-5250	4.7	7.71
			5250-5350	4.7	7.71
			5470-5725	4.7	7.71
			5725-5850	4.7	7.71
PCB	TAOGLAS	FXP831.07.0100C	2402-	3	6.01

Antenna Type	Supplier	Antenna part no.	Freq. (MHz)	Peak antenna gain (dBi)	Directional gain (dBi)
			2480		
			5150-5250	5.5	8.51
			5250-5350	5.5	8.51
			5470-5725	5.5	8.51
			5725-5850	5.5	8.51

* Antenna gain in free space

Note If using the RF module in a portable application (for example - if the module is used in a hand-held device and the antenna is less than 20 cm (8 in) from the human body when the device is in operation): The integrator is responsible for passing additional SAR (Specific Absorption Rate) testing based on FCC rules 2.1091 and FCC Guidelines for Human Exposure to Radio Frequency Electromagnetic Fields, OET Bulletin and Supplement C. The testing results will be submitted to the FCC for approval prior to selling the integrated unit. The required SAR testing measures emissions from the module and how they affect the person.

RF exposure



CAUTION! To satisfy FCC RF exposure requirements for mobile transmitting devices, a separation distance of 20 cm (8 in) or more should be maintained between the antenna of this device and persons during device operation. To ensure compliance, operations at closer than this distance are not recommended. The antenna used for this transmitter must not be co-located in conjunction with any other antenna or transmitter. The preceding statement must be included as a CAUTION statement in OEM product manuals in order to alert users of FCC RF Exposure compliance.

Operating frequency

- 802.11 b/g/n: 2412-2462 MHz
- 802.11 a/n/ac : 5150-5250 MHz; 5250-5350 MHz; 5470-5725MHz; 5725-5850 MHz
- Bluetooth : 2402-2480 MHz

Europe and UK

- 2.412 to 2.472 GHz; 13 channels
- 5.180 to 5.320 GHz; 8 channels
- 5.500 to 5.700 GHz, 8 channels (excludes 5.600 to 5.640 GHz)

CE mark

The ConnectCore MP13 module is certified for use in several European countries. For information, visit www.digi.com/resources/certifications.

If the ConnectCore MP13 module is incorporated into a product, the manufacturer must ensure compliance of the final product with articles 3.1a and 3.1b of the RE Directive (Radio Equipment Directive). A Declaration of Conformity must be issued for each of these standards and kept on file as described in the RE Directive (Radio Equipment Directive).

Furthermore, the manufacturer must maintain a copy of the ConnectCore MP13 module user manual documentation and ensure the final product does not exceed the specified power ratings, antenna specifications, and/or installation requirements as specified in the user manual. If any of these specifications are exceeded in the final product, a submission must be made to a notified body for compliance testing to all required standards.

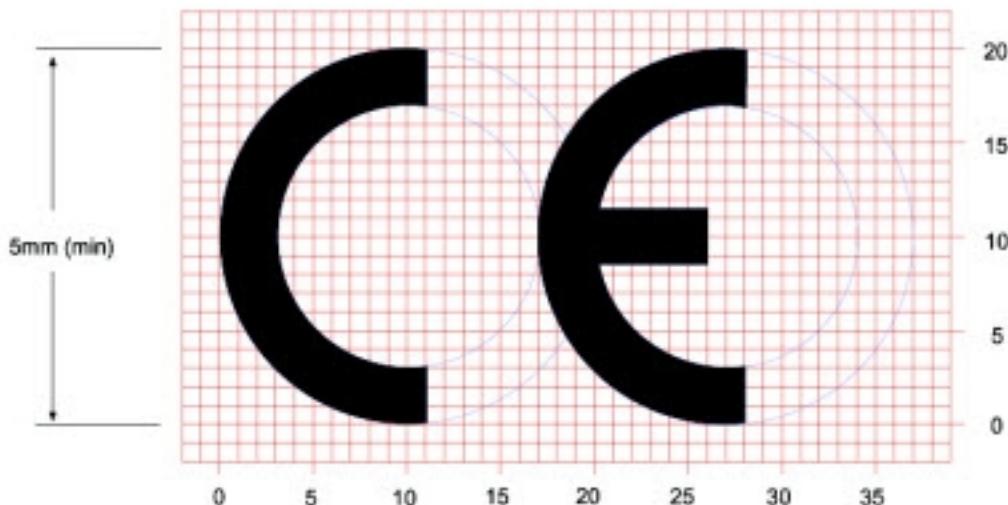
This equipment should be installed and operated with a minimum distance of 20 cm between the radiator and your body.

CE and UKCA OEM labeling requirements

The CE and UKCA markings must be clearly visible and legible when you affix it to the product. If this is not possible, you must attach these marks to the packaging (if any) or accompanying documents.

CE labeling requirements

The “CE” marking must be affixed to a visible location on the OEM product. The following figure shows CE labeling requirements.



The CE mark shall consist of the initials “CE” taking the following form:

- If the CE marking is reduced or enlarged, the proportions given in the above graduated drawing must be respected.
- The CE marking must have a height of at least 5 mm except where this is not possible on account of the nature of the apparatus.
- The CE marking must be affixed visibly, legibly, and indelibly.

UK Conformity Assessed (UKCA) labeling requirements

See <https://www.gov.uk/guidance/using-the-ukca-marking> for further details.

You must make sure that:

- if you reduce or enlarge the size of your marking, the letters forming the UKCA marking must be in proportion to the version set out below
- the UKCA marking is at least 5 mm in height – unless a different minimum dimension is specified in the relevant legislation
- the UKCA marking is easily visible, legible (from 1 January 2023 it must be permanently attached)
- the UKCA marking can take different forms (for example, the colour does not have to be solid), as long as it remains visible, legible and maintains the required proportions.

Important note

Digi customers assume full responsibility for learning and meeting the required guidelines for each country in their distribution market. Refer to the radio regulatory agency in the desired countries of operation for more information.

Declarations of Conformity

Digi has issued Declarations of Conformity for the ConnectCore MP13 module concerning emissions, EMC, and safety. For more information, see <http://www.digi.com/resources/certifications>.

Important note

Digi customers assume full responsibility for learning and meeting the required guidelines for each country in their distribution market. Refer to the radio regulatory agency in the desired countries of operation for more information.

Approved antennas

The same antennas have been approved for Europe as stated in the FCC table for use with the ConnectCore MP13 module.

Country list

				
AT	BE	BG	CZ	DK
EE	FR	DE	IS	IE
IT	EL	ES	CY	LV
LI	LT	LU	HU	MT
NL	NO	PL	PT	RO
SI	SK	TR	FI	SE
CH	UK	HR		

Note This device is restricted to indoor use only when operating in the 5150-5350MHz frequency range within all member states.

Radio Type / Description	Transmitter Frequency (MHz)	Maximum Output Power
Bluetooth	2402 ~ 2480	15.86 dBm
	2402 ~ 2480	6.88 dBm
WLAN 2.4G	2412 ~ 2472	19.24 dBm
	2412 ~ 2472	19.31 dBm
	2412 ~ 2472	19.54 dBm
	2422 ~ 2462	19.45 dBm
WLAN 5G	5150 ~ 5350	22.16 dBm
	5470 ~ 5725	21.99 dBm
	5725 ~ 5850	13.17 dBm
	5150 ~ 5350	22.22 dBm
	5470 ~ 5725	22.00 dBm
	5725 ~ 5850	13.16 dBm
	5150 ~ 5350	22.55 dBm
	5470 ~ 5725	21.82 dBm
	5725 ~ 5850	13.28 dBm
	5150 ~ 5350	21.52 dBm
	5470 ~ 5725	20.90 dBm
	5725 ~ 5850	13.15 dBm

Canada (IC)

IC: 1846A-CCMP1

PMN: ConnectCore MP13

HVIN: 55002163-XX

Canadian Notice

This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the following two conditions:

1. This device may not cause interference.
2. This device must accept any interference, including interference that may cause undesired operation of the device.

Avis Canadien

L'émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

1. L'appareil ne doit pas produire de brouillage;
2. L'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Labeling requirements

Labeling requirements for Industry Canada are similar to those of the FCC.

Required End Product Labeling

Any device incorporating this module must include an external, visible, permanent marking or label which states:

“Contains IC : 1846A-CCMP1”

Obligation d'étiquetage du produit final:

Tout dispositif intégrant ce module doit comporter un externe, visible, marquage permanent ou une étiquette qui dit:

“Contient IC : 1846A-CCMP1”

Transmitters with detachable antennas

This radio transmitter (IC: 1846A-CCMP1) has been approved by Industry Canada to operate with the antenna types listed in the table above with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Le présent émetteur radio (IC: 1846A-CCMP1) a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types

d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the

equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

The ConnectCore MP13 module is for professional (OEM) installation only.

Le module ConnectCore MP13 doit impérativement être installé par un professionnel (OEM).

RF exposure

 To satisfy Industry Canada RF exposure requirements, a separation distance of 20 cm or more should be maintained between the antenna of this device and persons during device operation.

Pour satisfaire aux exigences d'Industrie Canada concernant l'exposition RF, une distance égale ou supérieure à 20cm doit être respectée entre les antennes de ce produit et les personnes se trouvant à proximité.

The preceding statement must be included as a CAUTION statement in OEM product manuals in order to alert users of Industry Canada RF Exposure compliance.

Cette information doit être incluse dans le manuel du produit OEM afin d'alerter les utilisateurs sur la nécessité de respecter l'exposition RF d'Industrie Canada.

Approved antennas

The same antennas have been approved for Canada as stated in the FCC table for use with the ConnectCore MP13 module.

Japan

電波法により5GHz帯は屋内使用に限ります。

This device has been granted a designation number by Ministry of Internal Affairs and Communications according to:

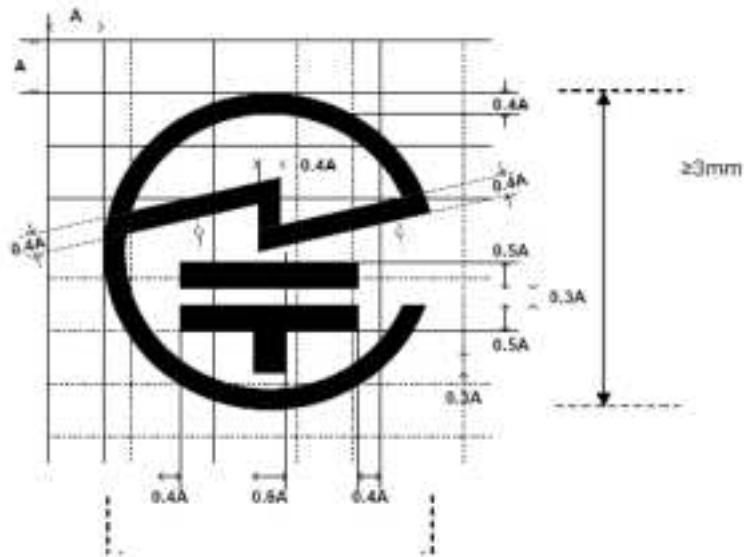
Ordinance concerning Technical Regulations Conformity Certification etc. of Specified Radio Equipment (特定無線設備の技術基準適合証明等に関する規則).

- Article 2, Paragraph 1, Item 19, 19-3, 19-3-2 Category: WW, XW, YW
- Model/Name of equipment: ConnectCore MP13
- Radio label marking:
 - R: 210-207701

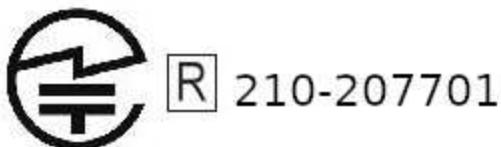
This device should not be modified (otherwise the granted designation number will be invalid).

- 2.412 to 2.472 GHz; 13 channels
- 5.180 to 5.320 GHz; 8 channels
- 5.500 to 5.700 GHz; 11 channels

Approval Label (MIC Marking)



Label text



Note Due to space constraints, the ConnectCore MP13 module label doesn't support radio marking for Japan. If space allows, end product label should support radio marking for Japan. If not, radio marking shall be documented in the user manual.

Note The warning “Indoor only(5GHz)” must go on the end product – or E Label (Display).

Master station: Indoor only

親局: 当該無線設備の送信は、屋内のみにおいて使用可能である旨

Slave station: The transmission of radio equipment is indoors use only (Except when communicating with 5.2GHz high power base stations or relay stations)

子局:当該無線設備の送信は、5.2GHz帯高出力データ通信システムの基地局 または陸上移動中継局 と通信する場合を除き、屋内においてのみ可能である旨。

If the device is too small it can be displayed on the user manual and on the packaging or container.